

Electrochemical Fabrication of Nanostructures and Their Fragments

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Original results used in this overview were obtained in collaboration with Dr Kirill Napolskii and his group

<https://www.eng.fnm.msu.ru/en/>

Outline

Electrochemical vs chemical fabrication techniques: higher complexity, but better controllability

Electrodeposition of low-dimensional fragments/materials for nm-and μm -scale devices

- „underpotential“ deposition: electrochemical ALD
- templated electrodeposition

Template-less localized processes

- local electrodeposition
- local electrochemical etching (dissolution)

Anodization (oxide formation)

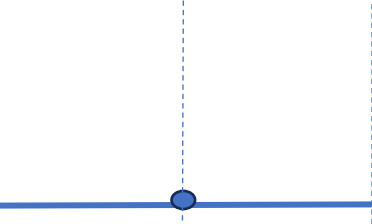
Control and monitoring tools

**Important advantage:
room temperature**

Current,
charge



“underpotential”
deposition (UPD)



Current,
charge



**Principle limitation:
only conducting supports**

**Limitation for ‘dry’ devices:
residual solvent**

Equilibrium
potential for
 M^{n+}/M redox
couple



Known from EMF
measurements

Potential regulates reaction rates (current)

Charge allows to monitor the amount of products

Current-time dependence is specific for morphology evolution
<but its interpretation requires certain models>

Potential
(free energy)

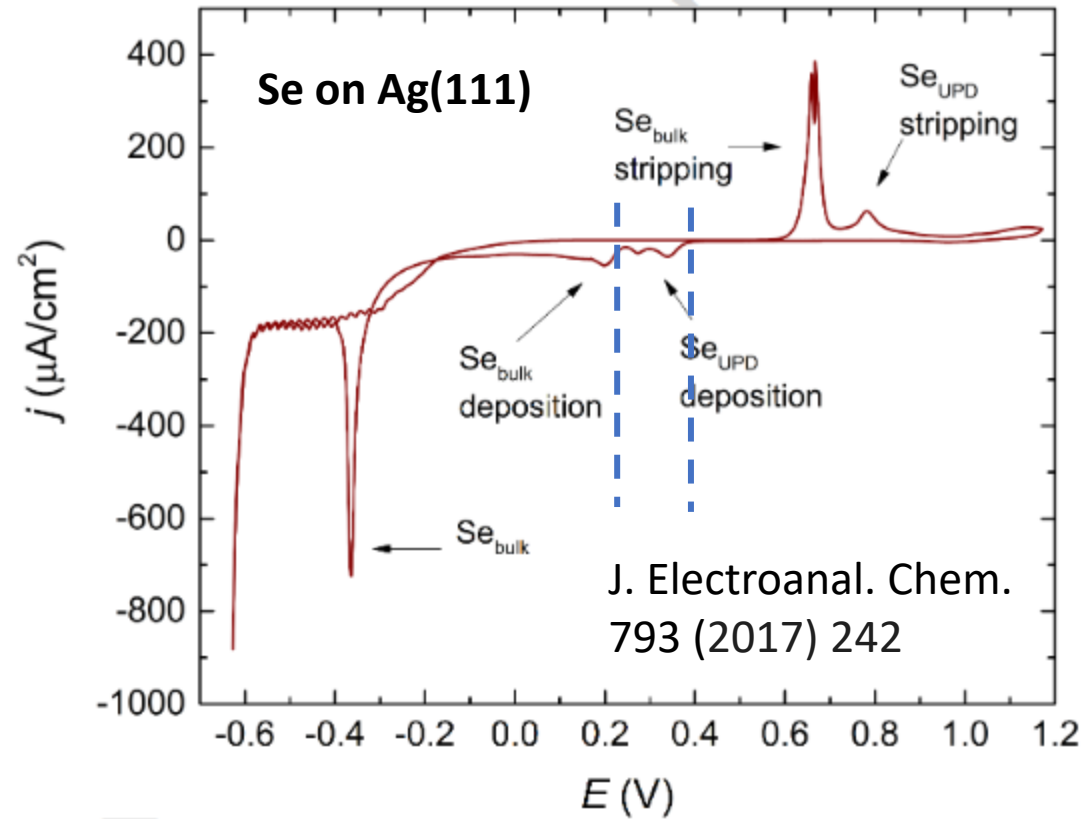
Galvanics
(electroplating, galvanoplastics)

Electropolishing, anodizing (color, protective), dimensional processing

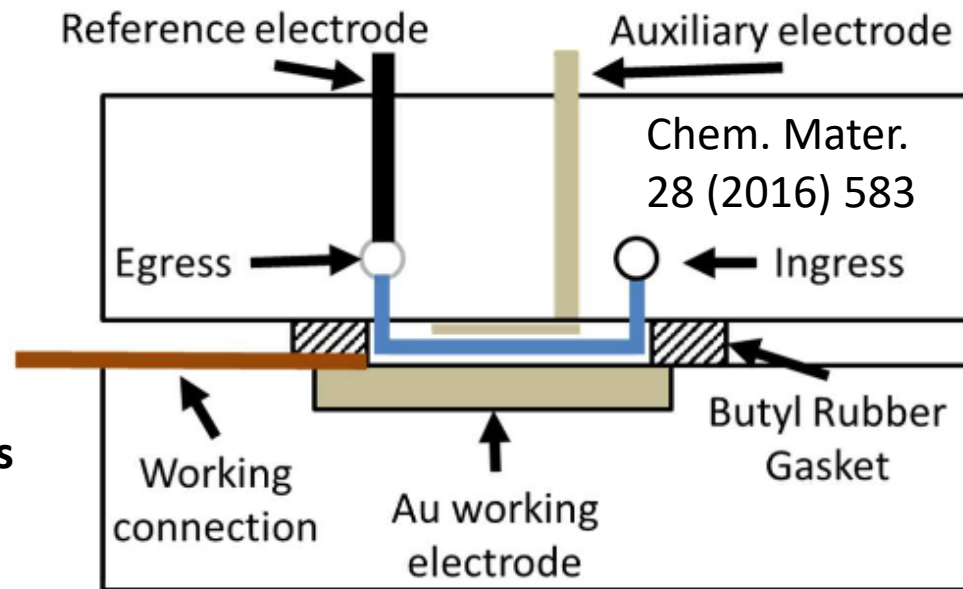
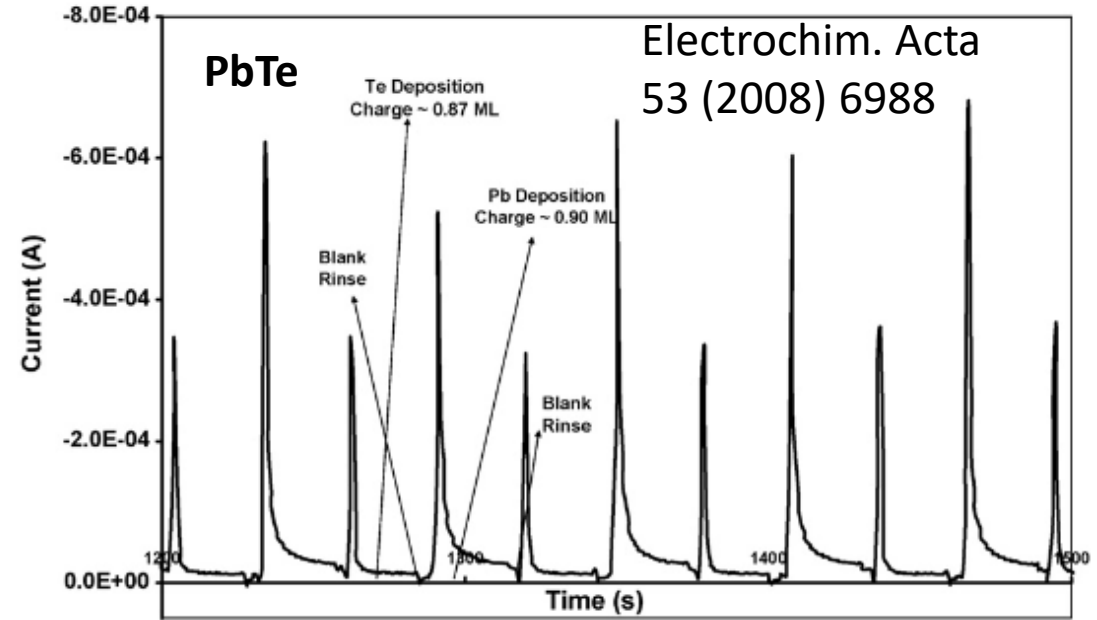
Traditional surface finishing

Surface-limited deposition (electrochemical ALD): “underpotential” formation of monolayers

J.L. Stickney, Electrochemical atomic layer epitaxy (EC-ALE): Nanoscale control in the electrodeposition of compound semiconductors, in *Adv. Electrochem. Sci. Eng.* 2002, v.7.

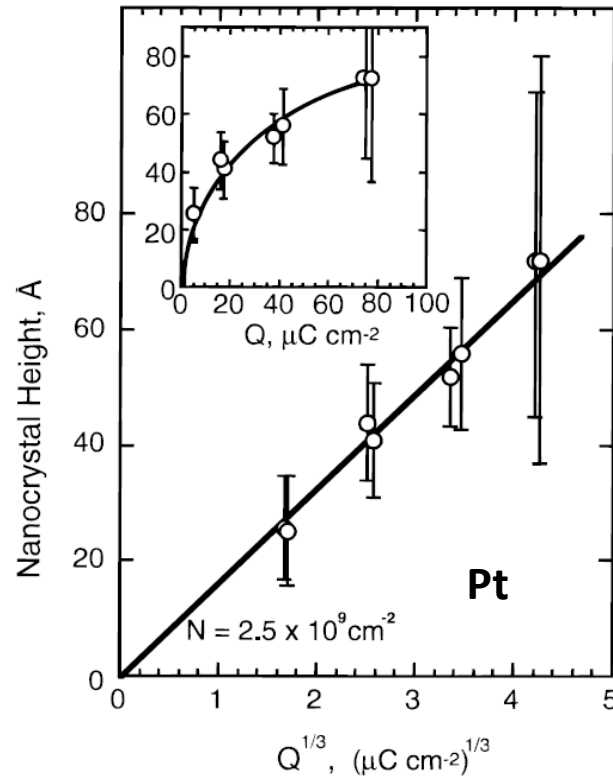
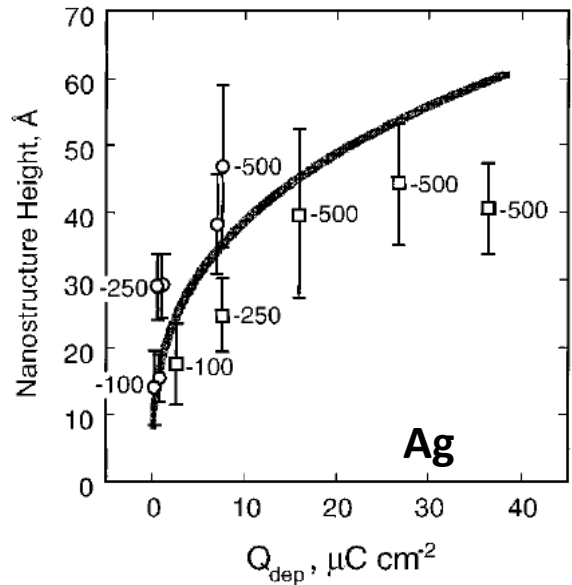
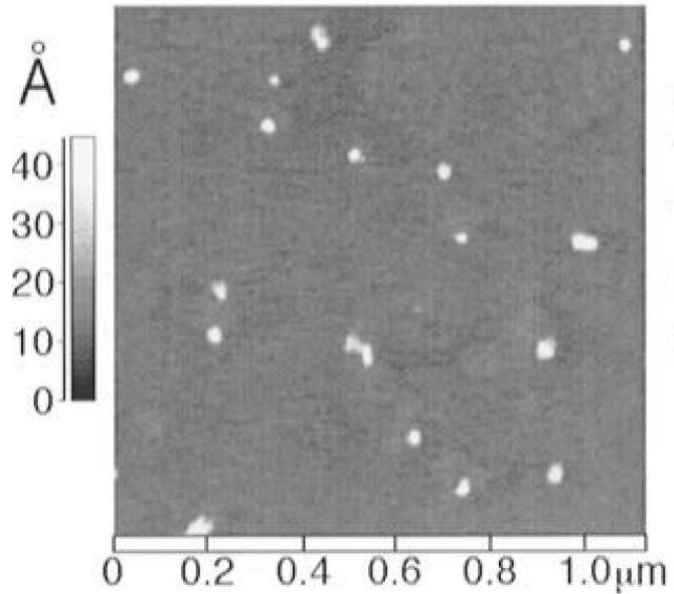


Charge for formation of adatoms monolayer is $\sim 200 - 400 \mu C/cm^2$



Flow cell for multilayer deposition (solutions of two reagents are introduced alternatively).

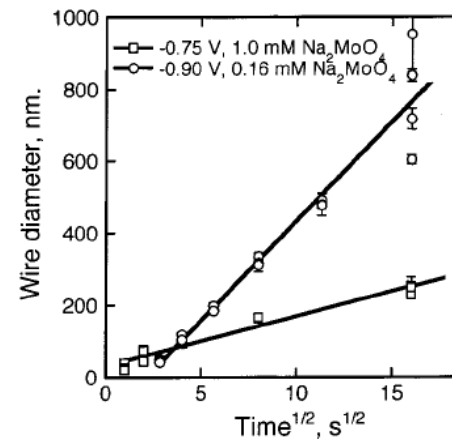
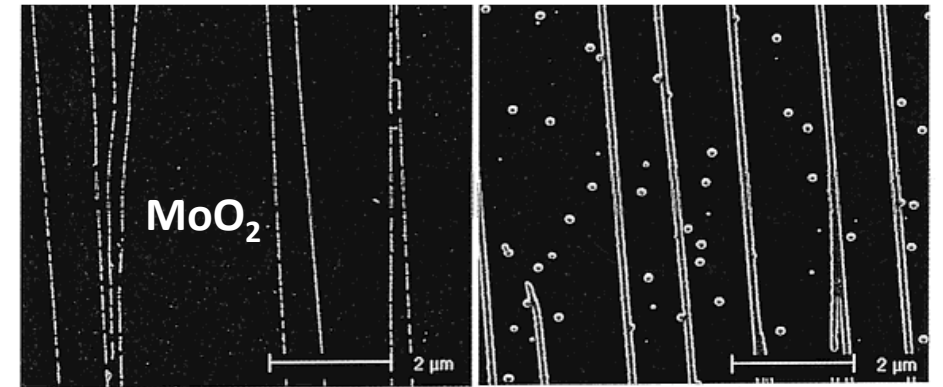
Initial electrodeposition steps: single particles and wires (nucleation and growth on HOPG)



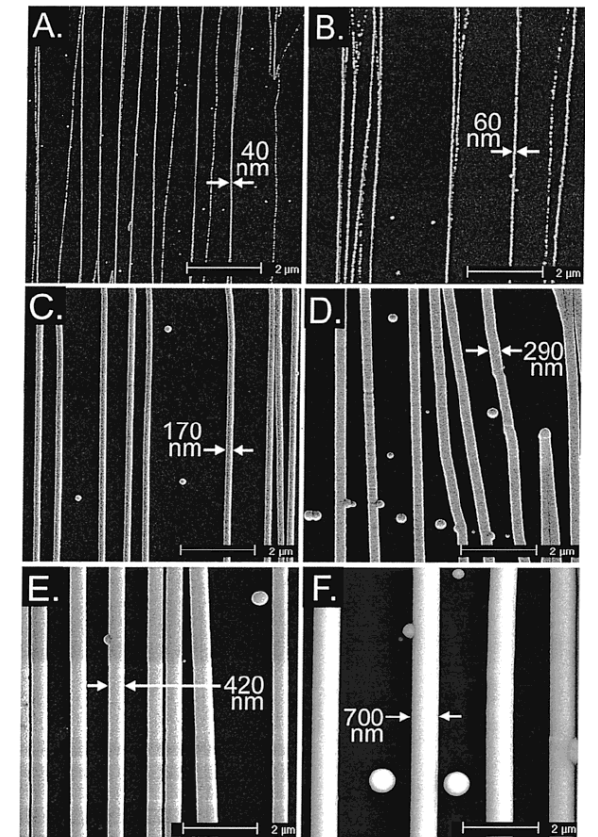
J. Phys. Chem. B
102 (1998) 1160

J. Phys. Chem.
100 (1996) 837

R.M. Penner et al.



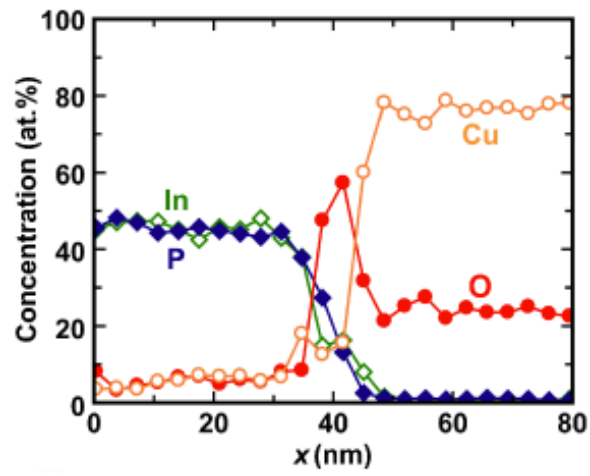
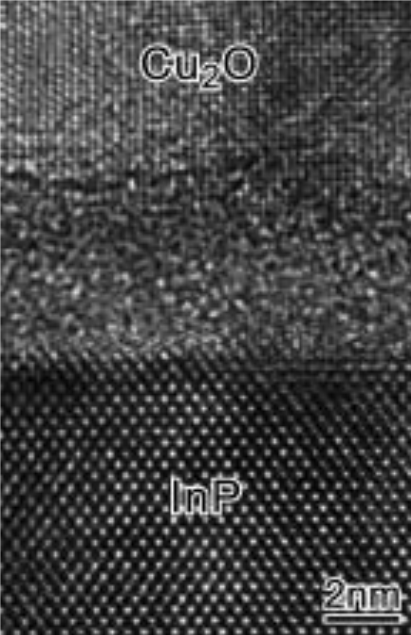
Step decoration,
Chem. Mater.
14 (2002) 3206



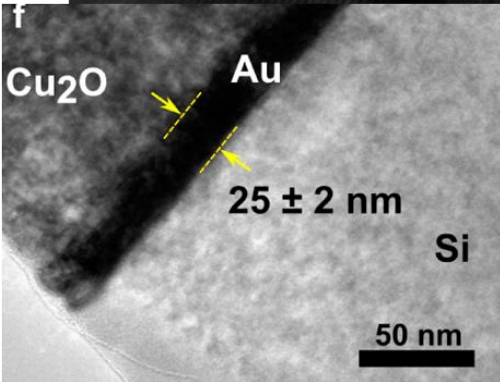
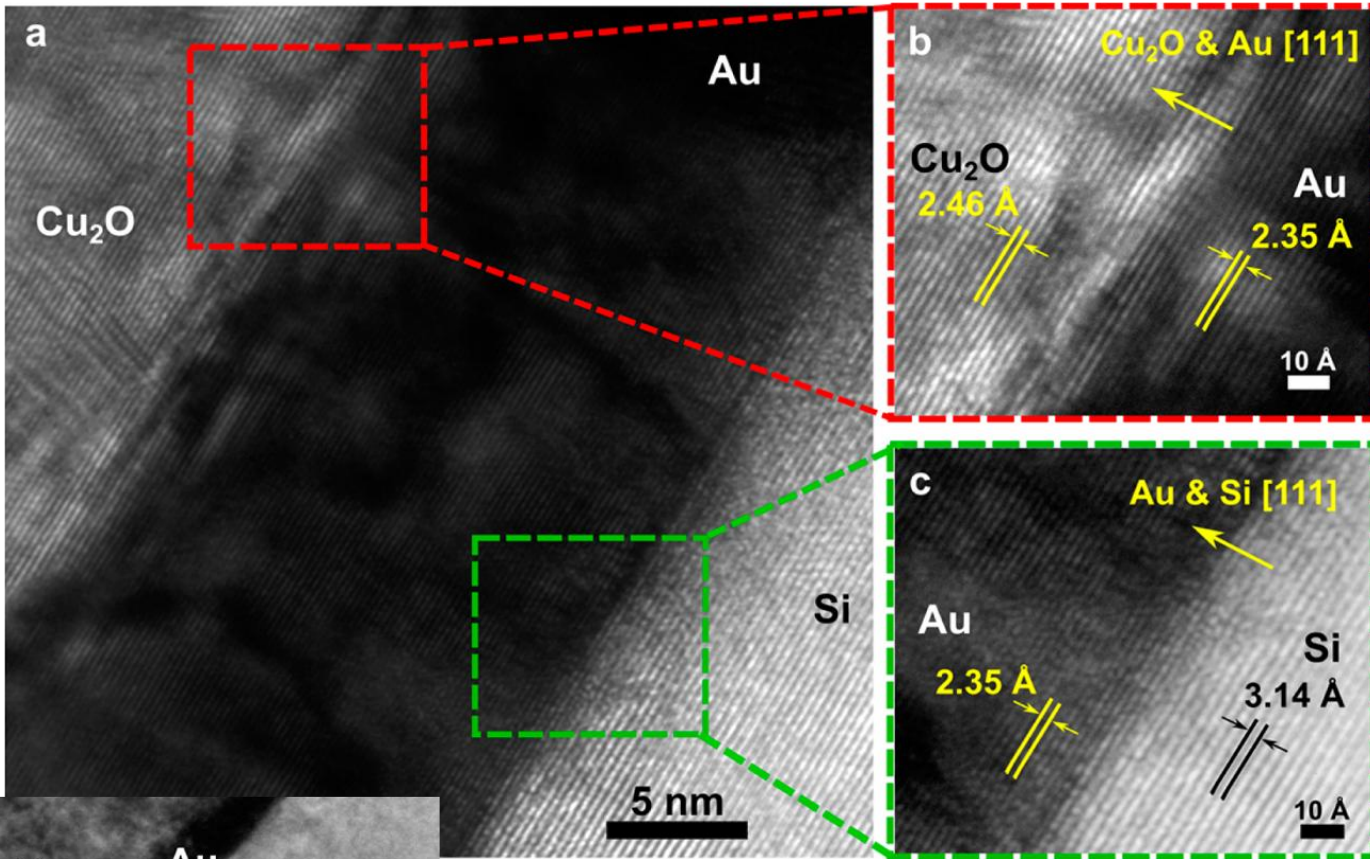
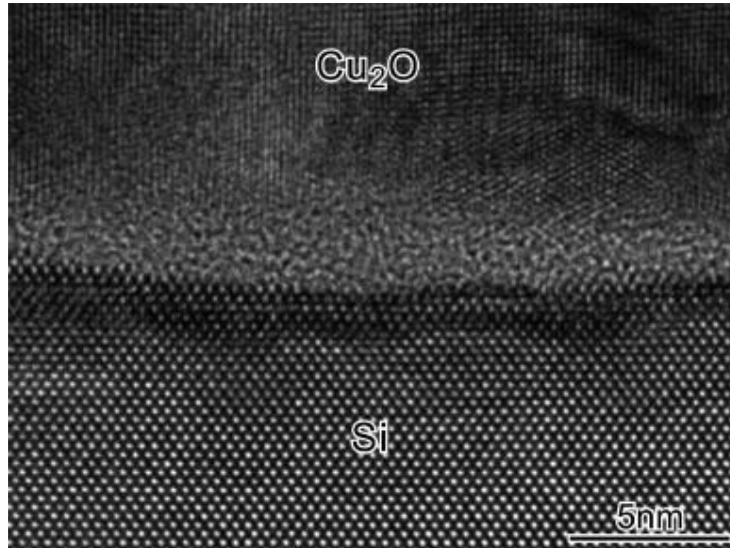
Oxides, sulfides, and selenides can be also electrodeposited <conducting polymers as well>

J. A. Switzer et al.

Problems with semiconductor supports



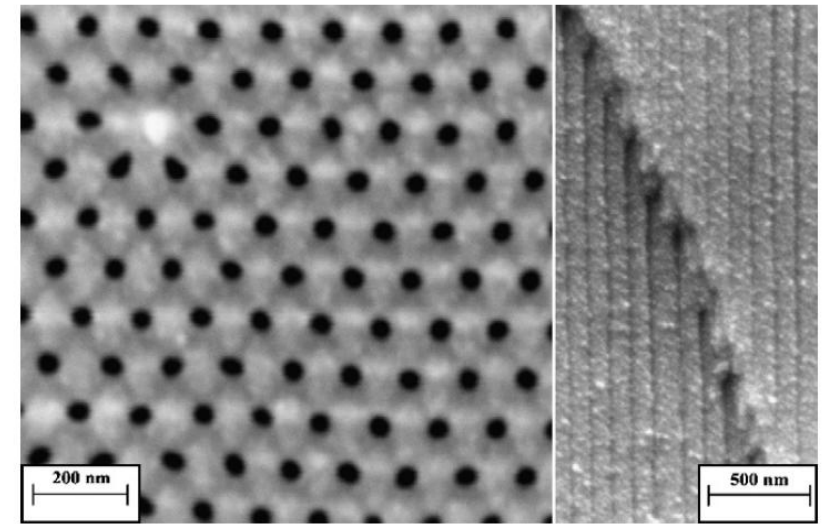
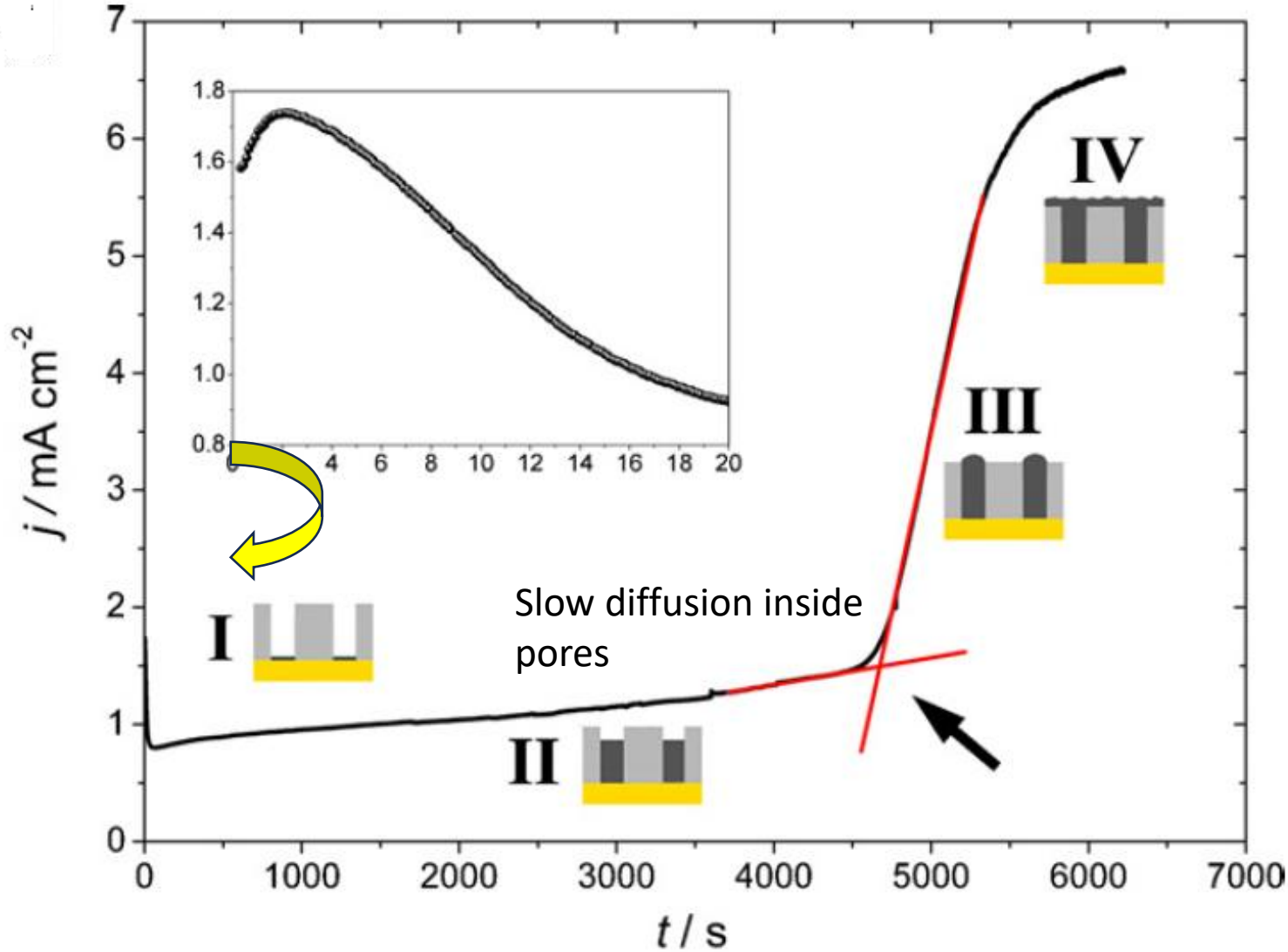
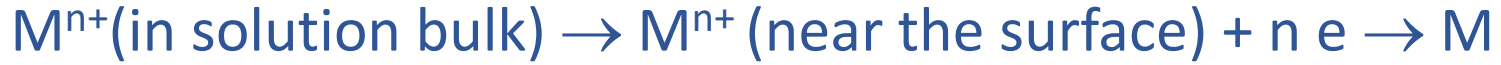
J. Am. Ceram. Soc.
88 (2005) 253



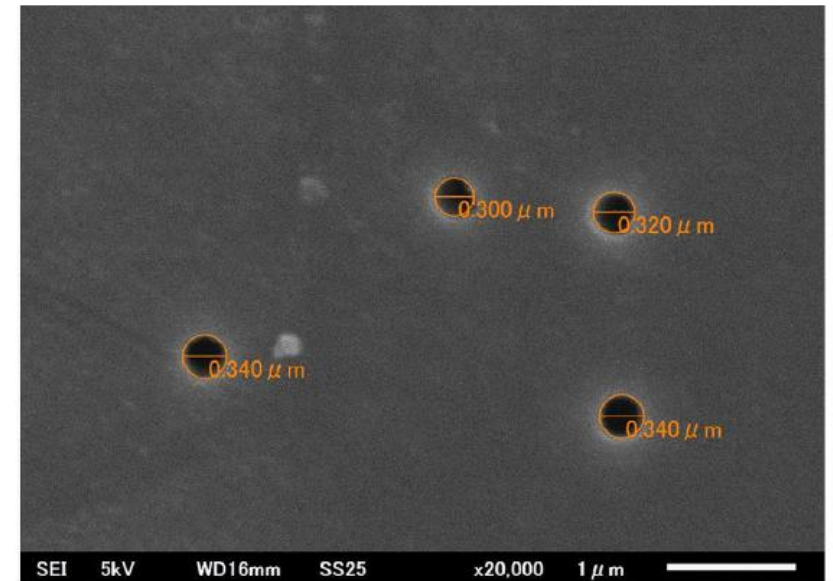
Much better with metal interlayer

ACS Appl. Mater. Interfaces
8 (2016) 15828

Templated deposition: spatial limitations of growth, wires

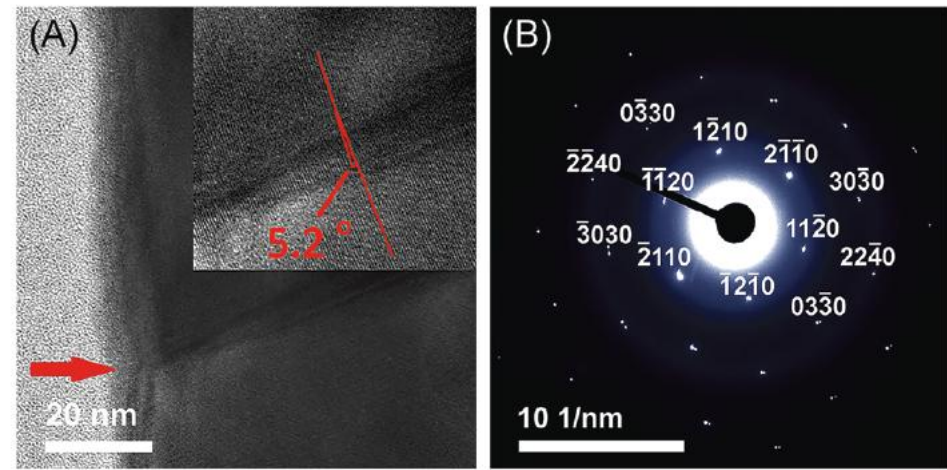
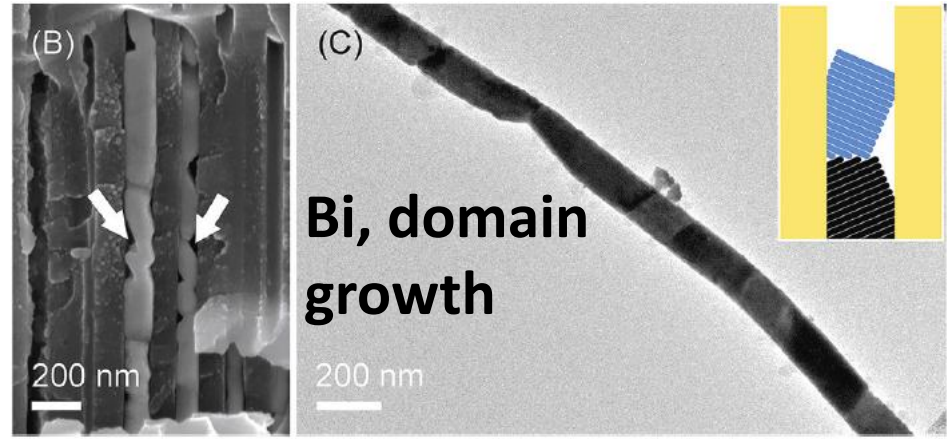
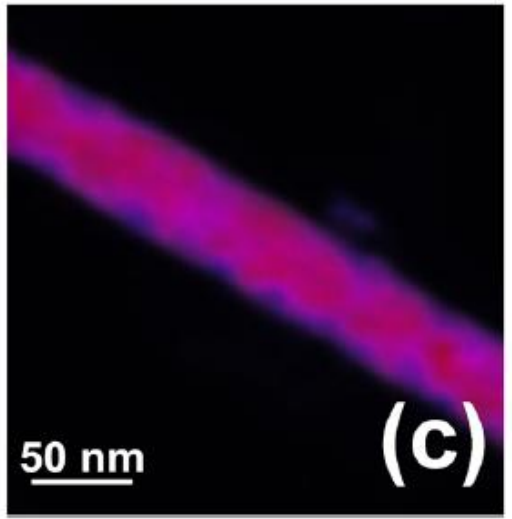
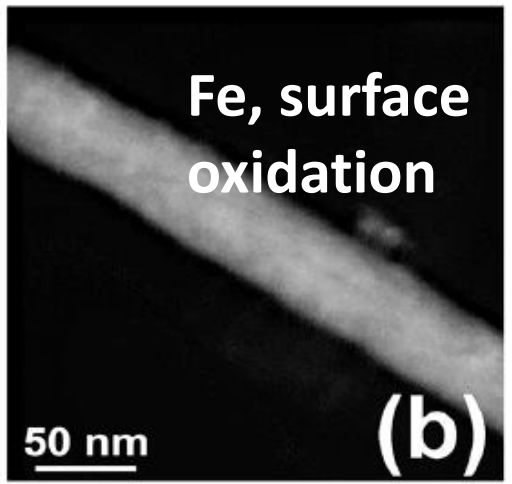
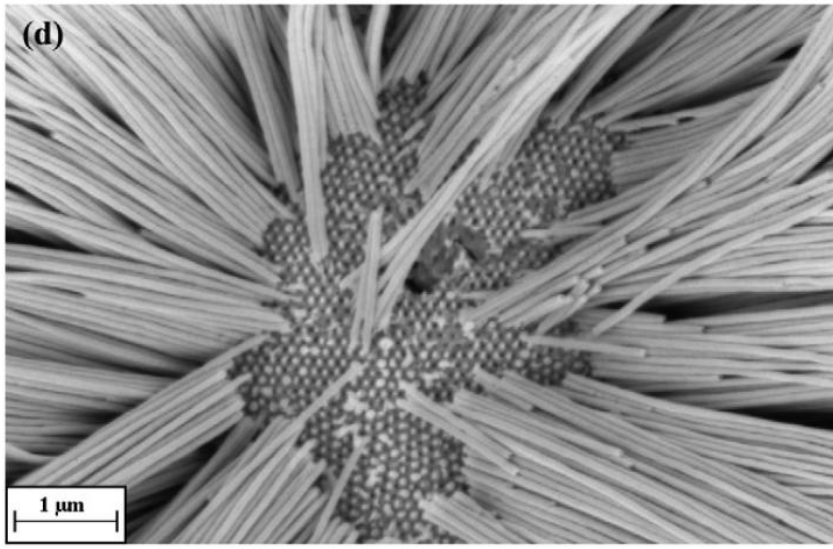
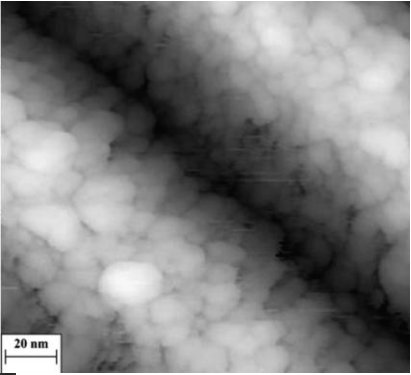
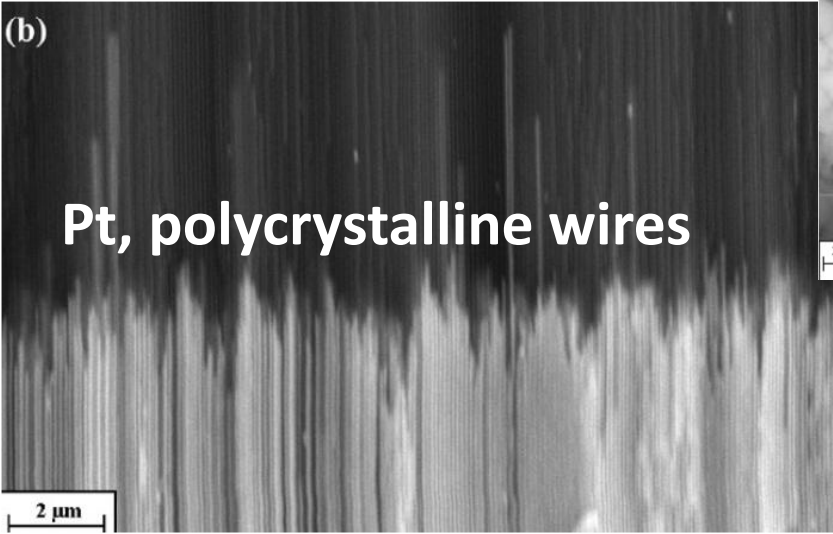


Anodic aluminum oxide (AAO),
Electrochim. Acta 52 (2007) 7910



Nucl. Instr. Meth. Physics Res. B
394 (2017) 121

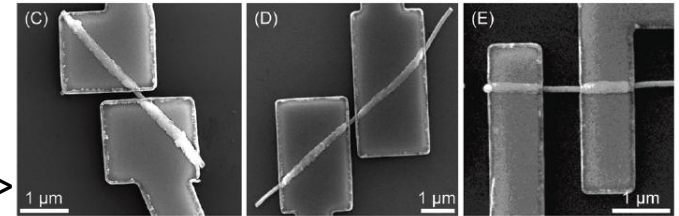
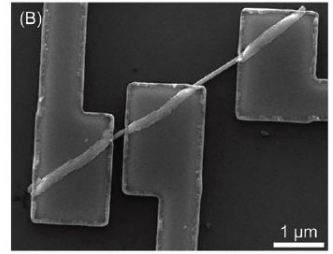
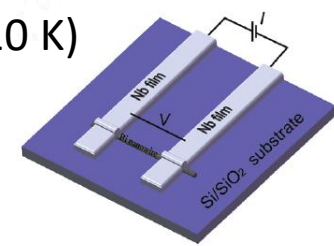
Wires: examples of problems



13-22 $\mu\text{Ohm} \cdot \text{m}$ (10 K)

PCCP
22 (2020) 14953

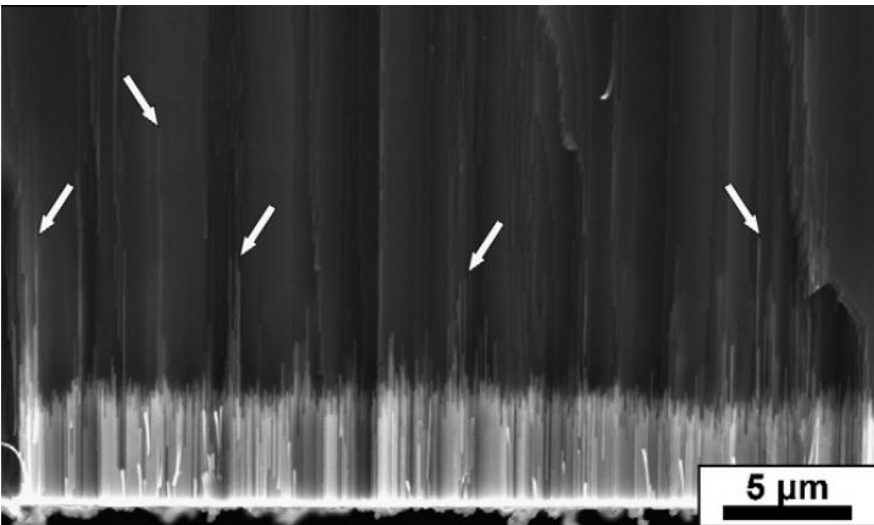
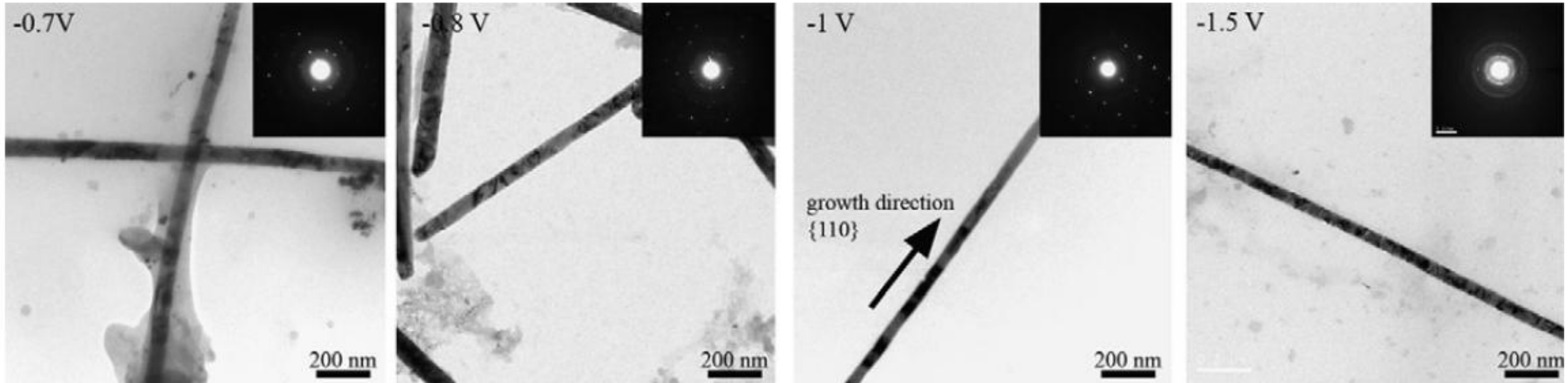
<low temperature
data in PRB
90 (2014) 245427>



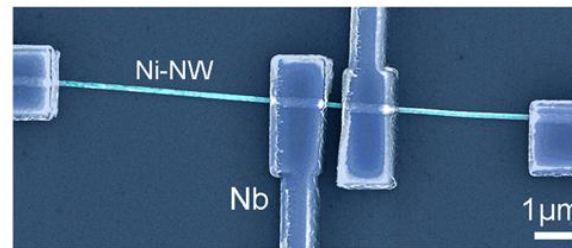
Electrochim. Acta 52 (2007) 7910

J. Sol-Gel Sci. Technol.
81 (2017) 327

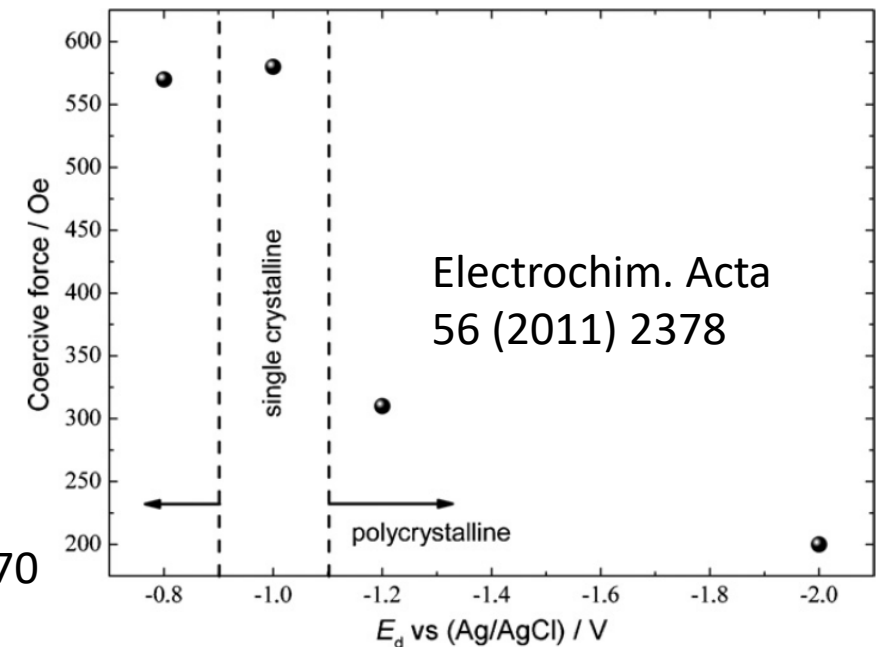
Wires: more lucky example (Ni), deposition potential effect on microstructure



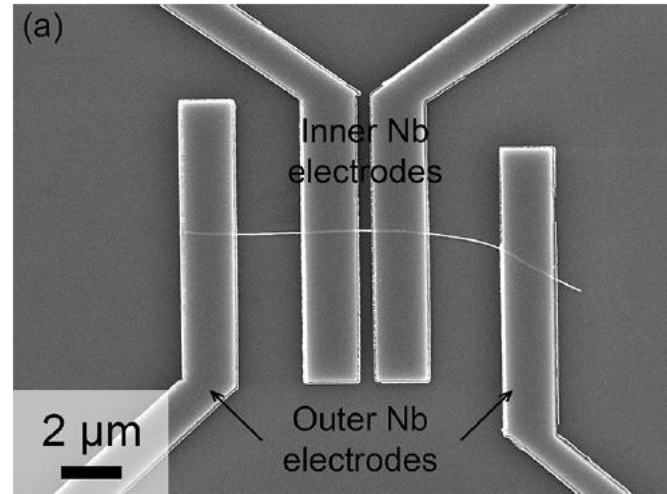
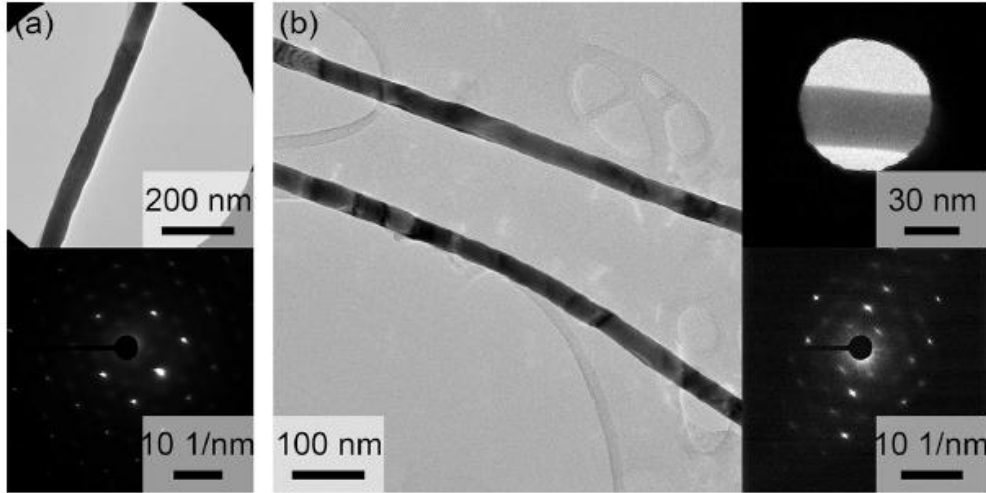
Growth front becomes less homogeneous at more negative potentials (higher growth rates)



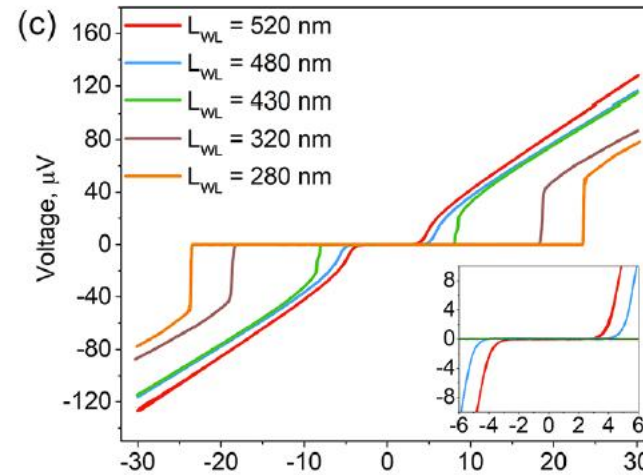
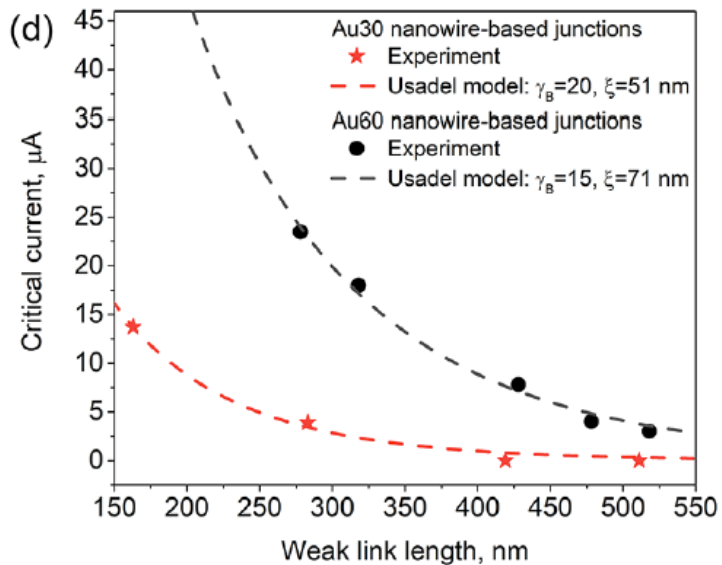
SFS junction: Sci. Rep. 9 (2019) 14470



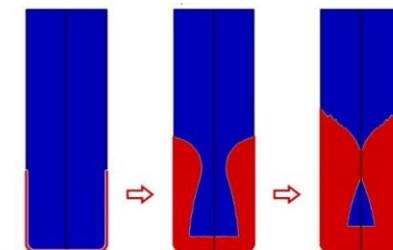
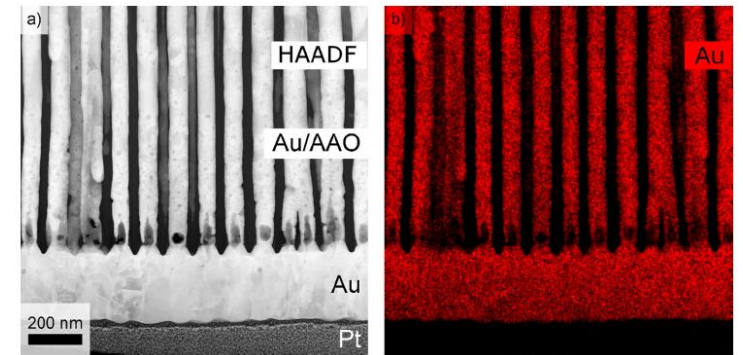
Wires: one more example (Au), the most promising?



Problems with initial part of wires were discovered when short wires were studied for magneto-optics <Opt. Lett. 43 (2018) 3917>



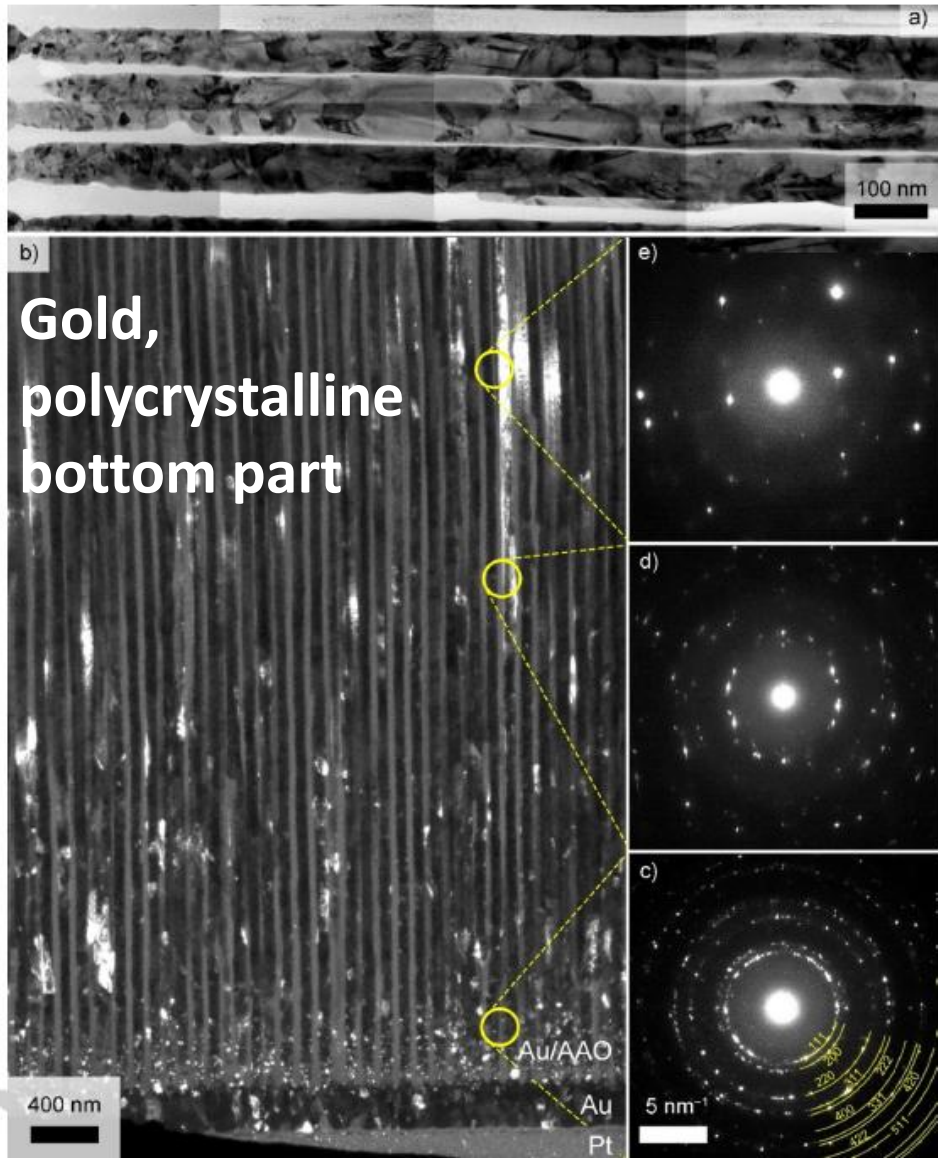
ACS Appl. Nano Mater. 5 (2022) 17059



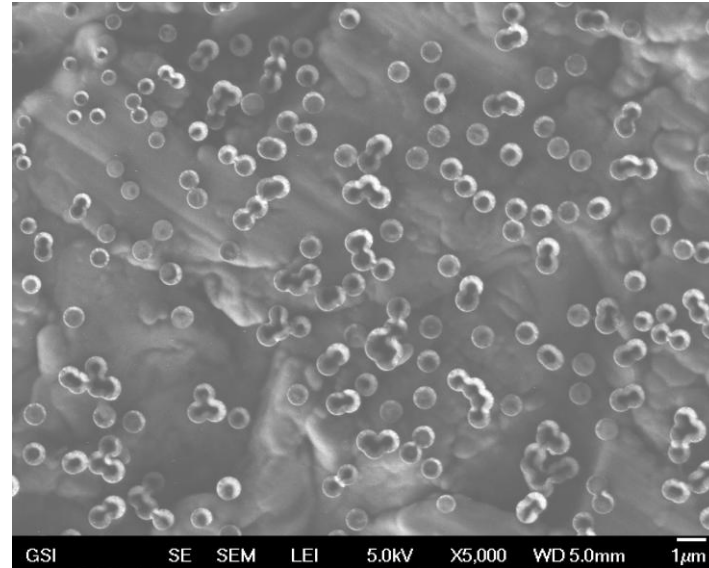
Growth starts from tubes

J. Solid State Electrochem. 2024

Wires: complications in the course of growth, at least two reasons:

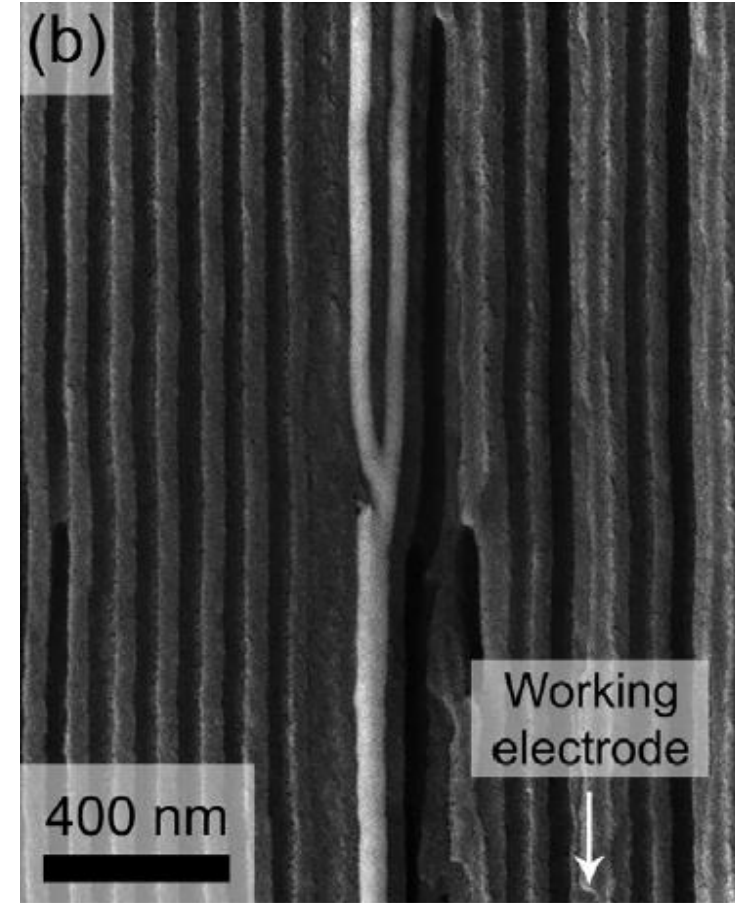


Geometry of conducting gold sublayer



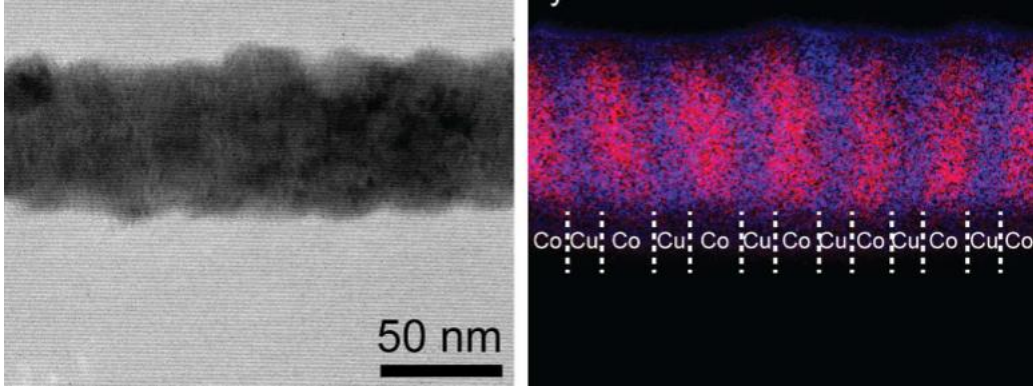
Back side of template with sputtered gold, which penetrates into the pores.

Imperfections of AAO

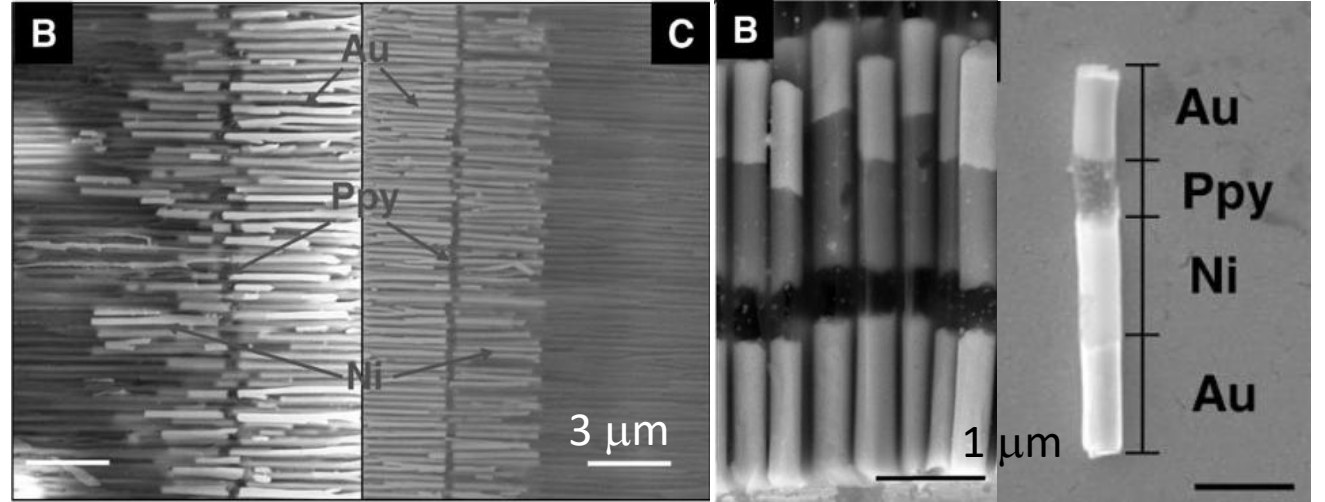


Electrochim. Acta 226 (2017) 60

Wires: prospects of heterojunctions



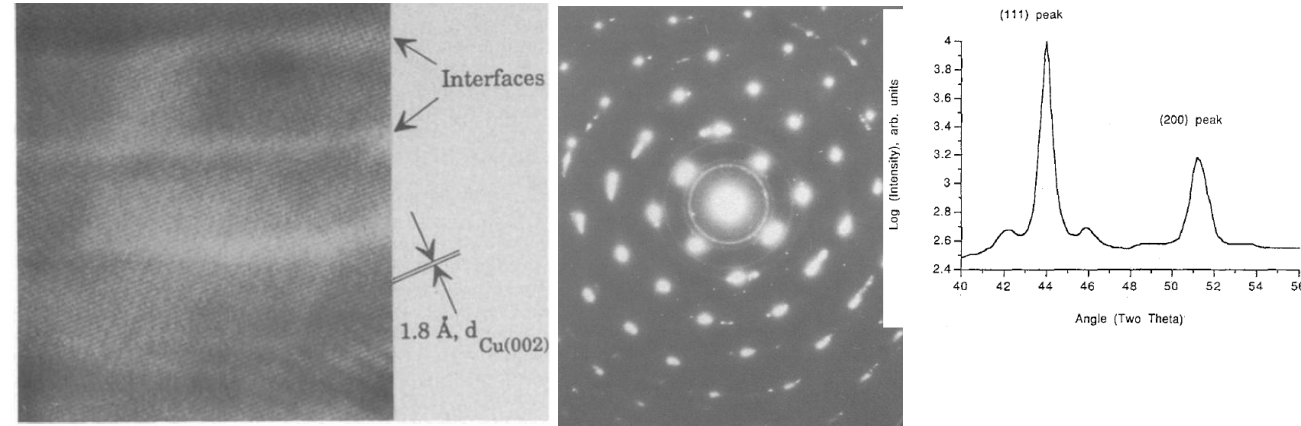
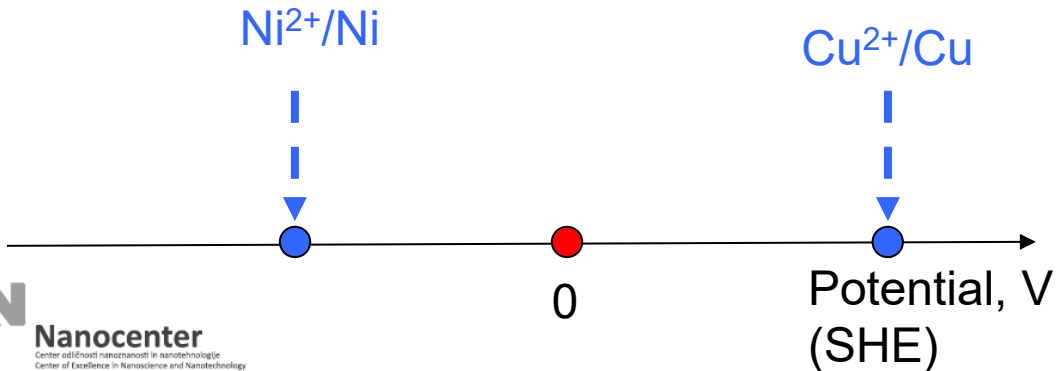
Cobalt/copper, Nano Lett. 16 (2016) 1230



Gold/polypyrrole/nickel/gold, Electroanalysis 21 (2009) 61

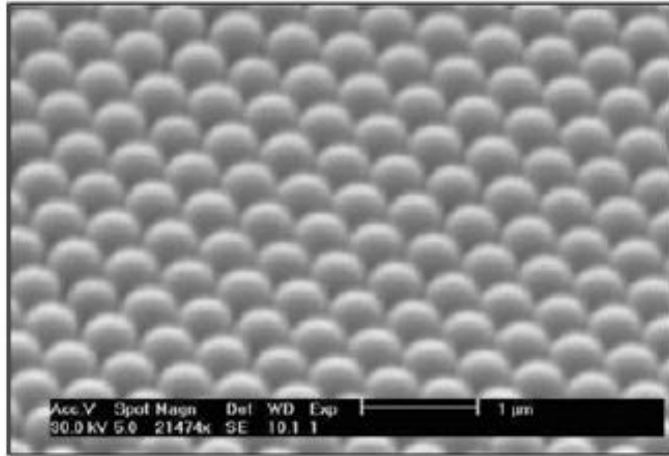
Old experience of electrochemical deposition of bimetallic superlattices: single or dual bath

“Single bath” requires numerous changes of solution.
 “Dual bath” assumes Cu:Ni ratio in solution ~ 1:100, for slower Cu deposition.

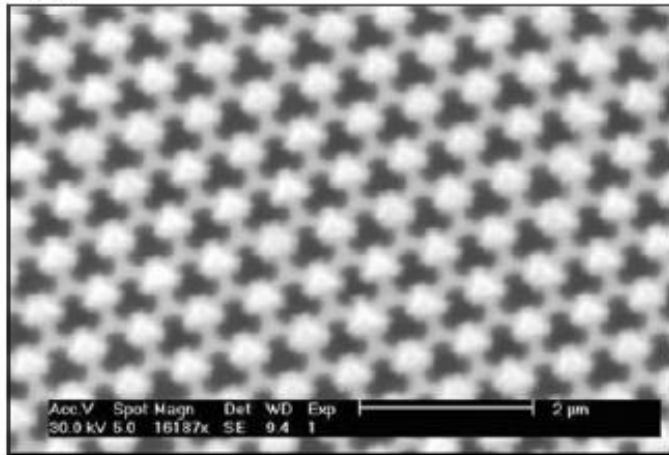


J. Electrochem. Soc. 135 (1988) 1218; 141 (1994) 230

Templated deposition: polystyrene spheres, inverse opals are formed

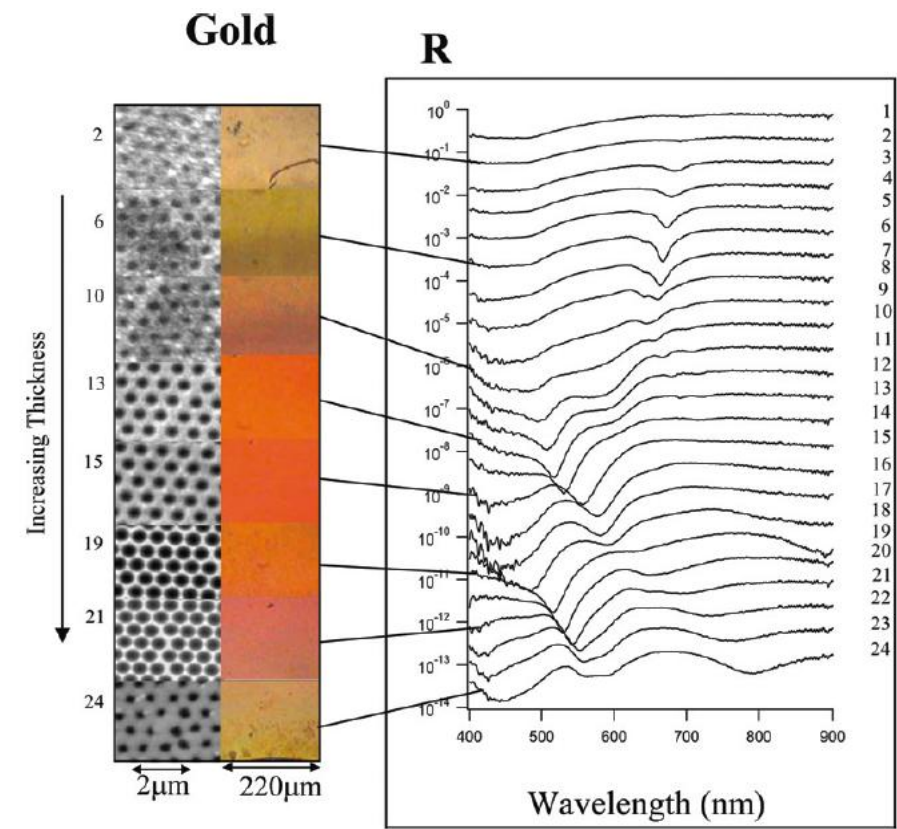
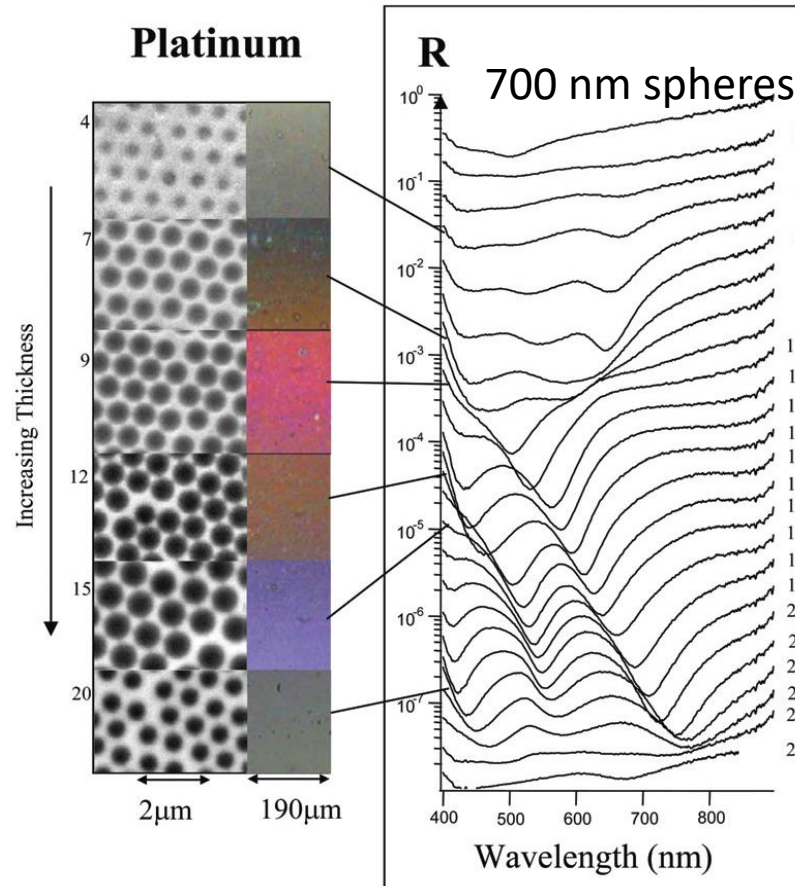


Polystyrene self-assembly

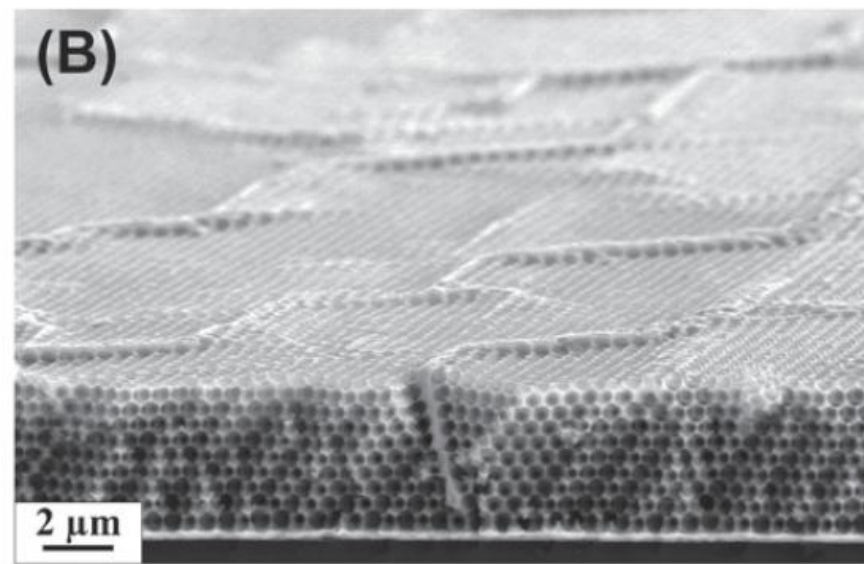
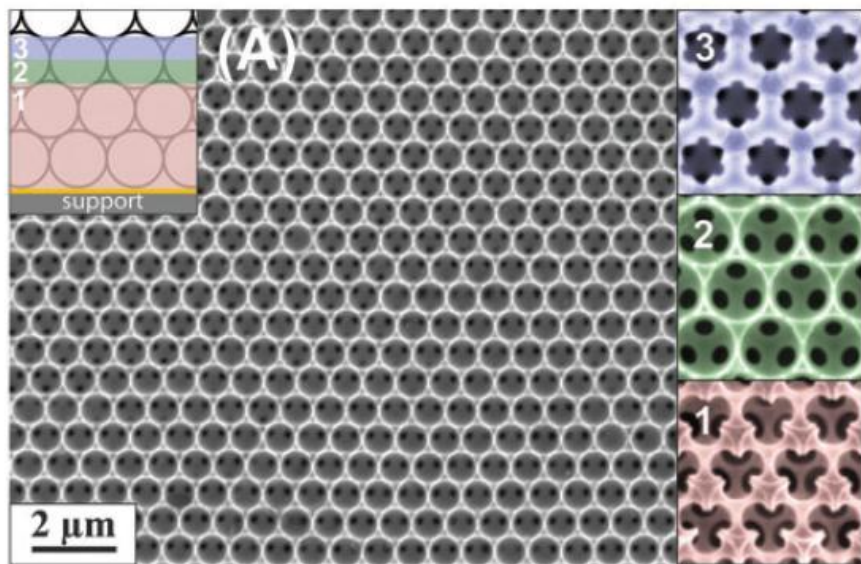
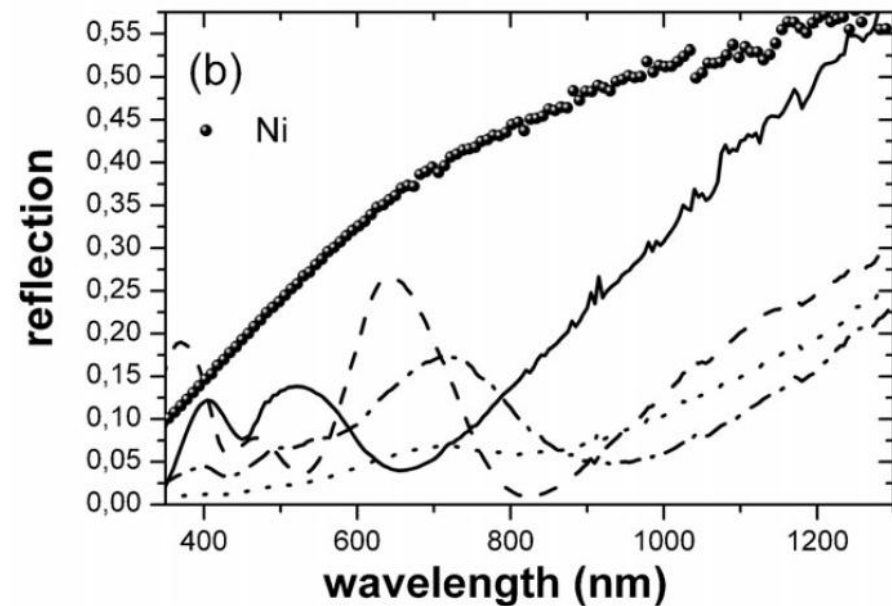
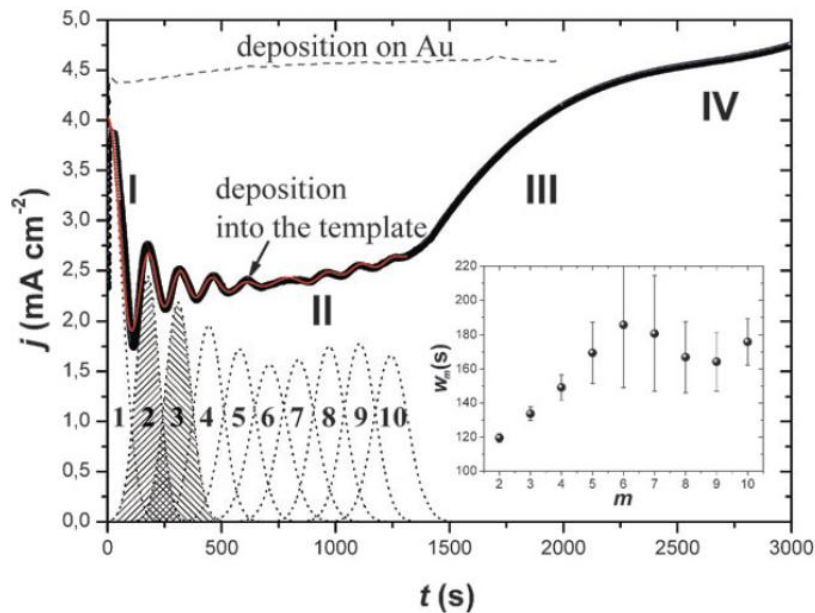
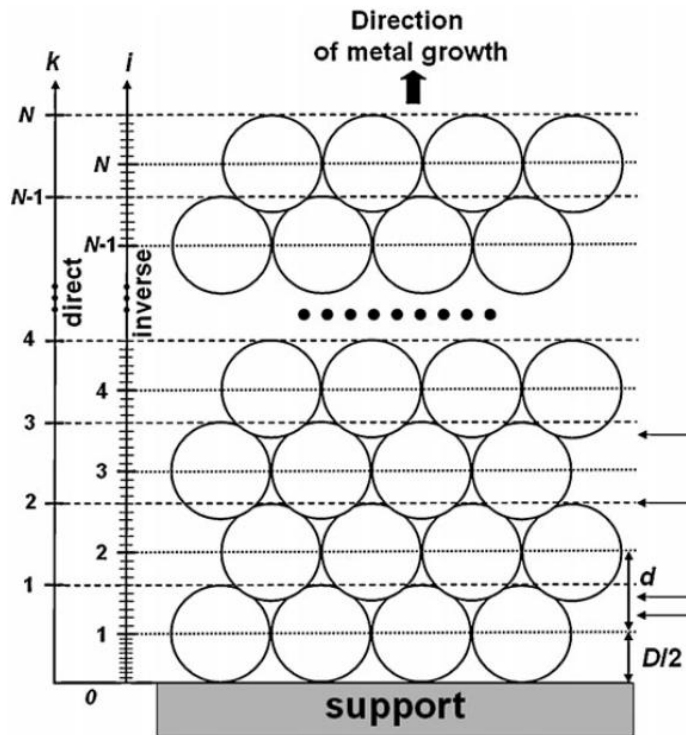


Metal after deposition and dissolution of polystyrene

P.N. Bartlett et al., Optical properties of nanostructured metal films, Faraday Discuss. 125 (2004) 117



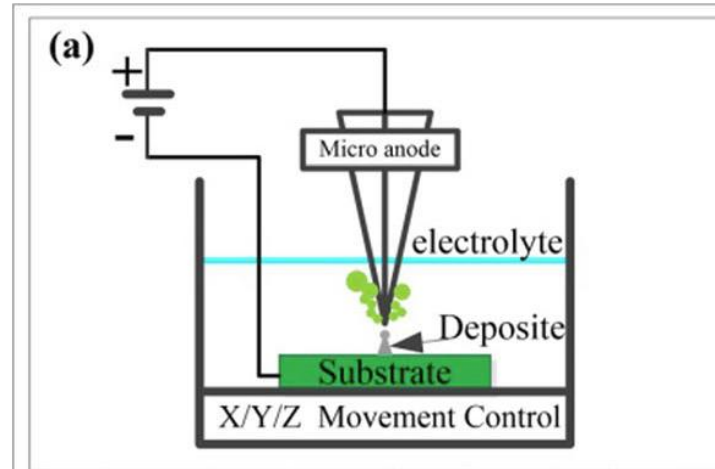
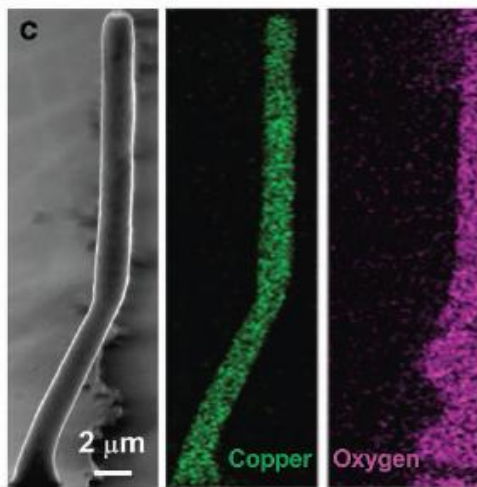
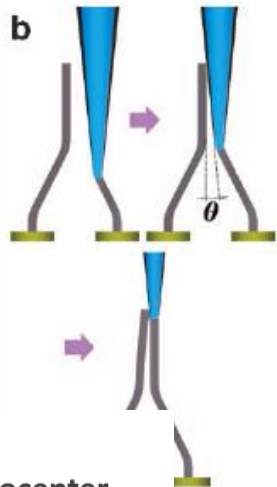
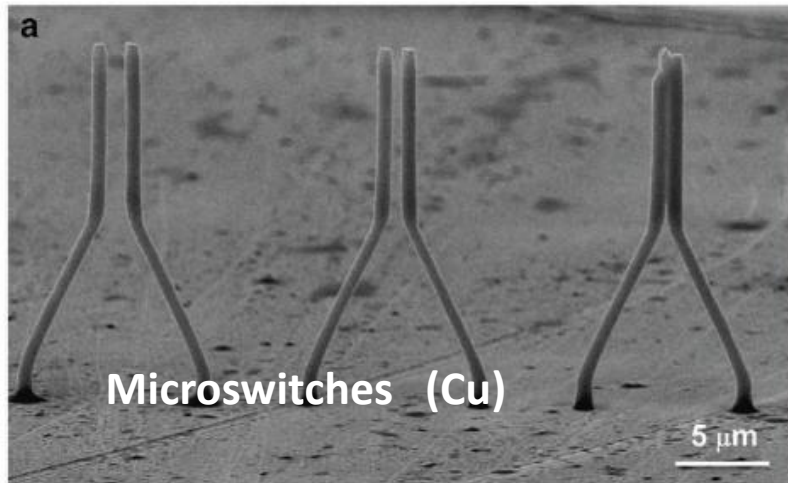
Templated deposition of inverse opals: monitoring



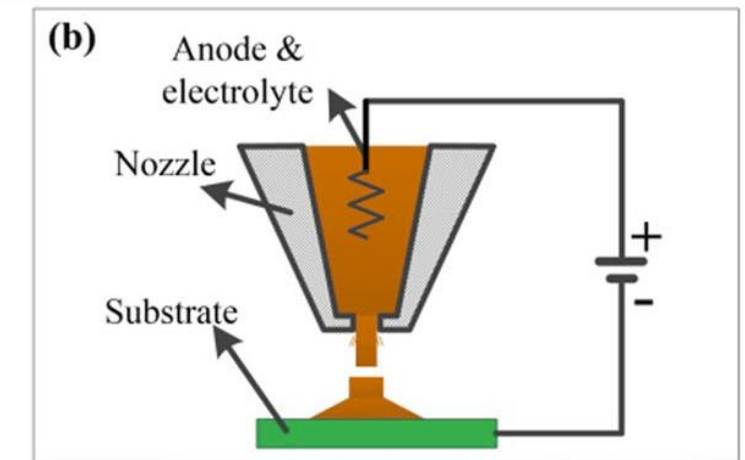
Maskless localized electrodeposition: microelectrodes (in probe microscopes as well) or micropipettes

Review: Int. J. Adv. Manuf. Technol. 110 (2020) 1731–1757

Microsyst. Nanoeng. 2 (2016) 16010

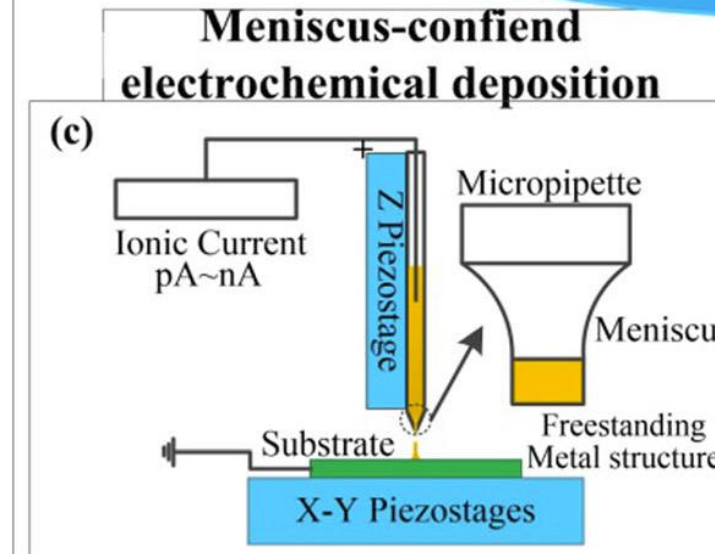


Localized electrochemical deposition

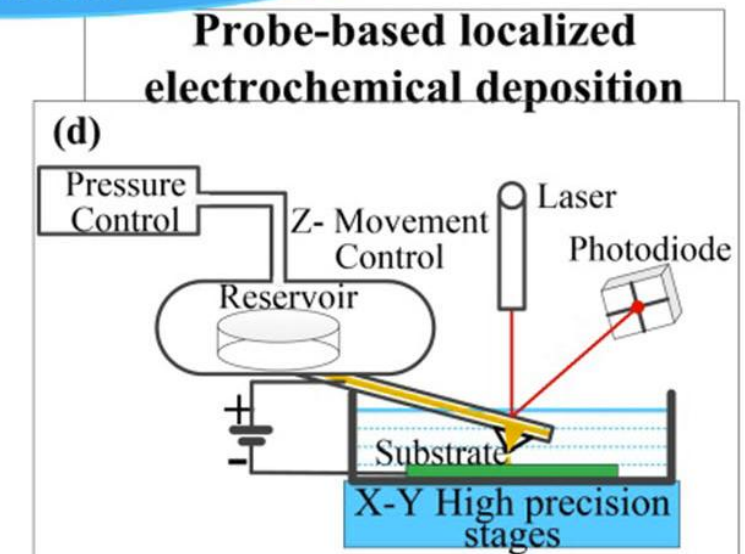


Electrochemical printing

Maskless Localized Electrochemical Deposition

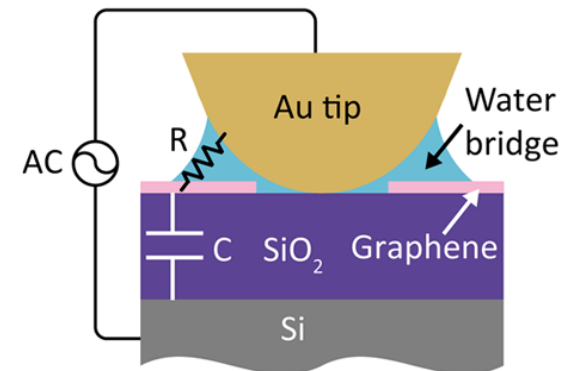
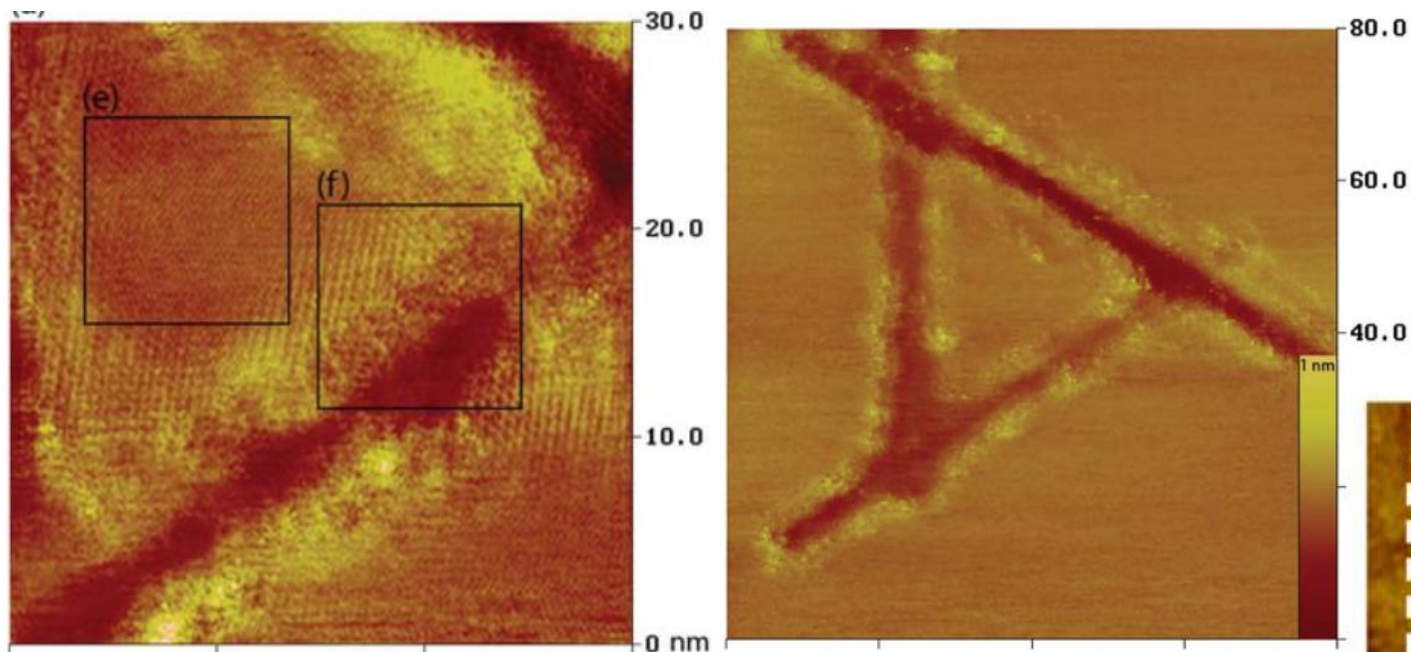


Meniscus-confined electrochemical deposition

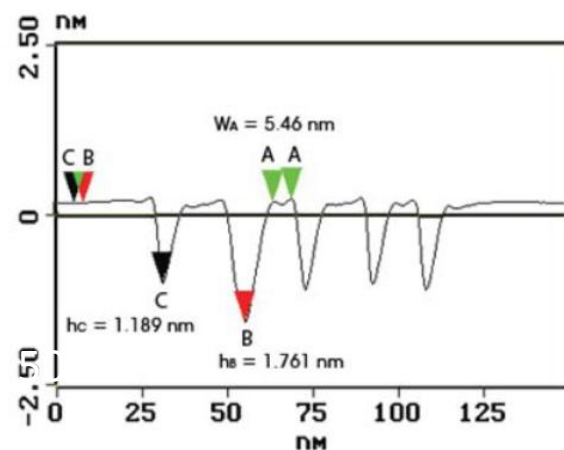
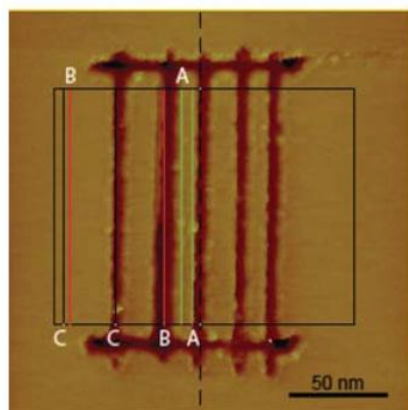
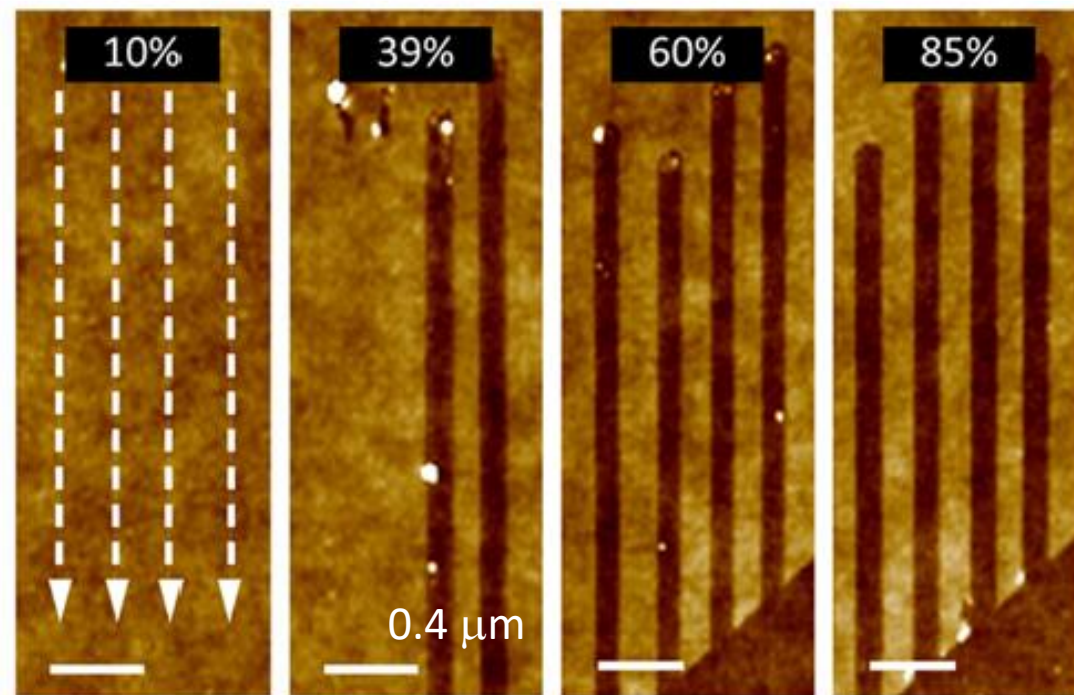


Probe-based localized electrochemical deposition

Cutting graphene with STM tip in condensed water layer

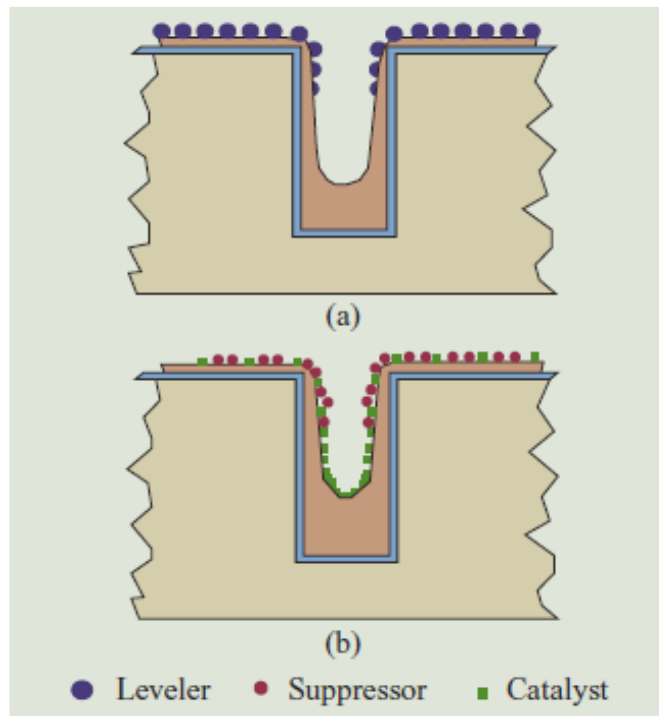
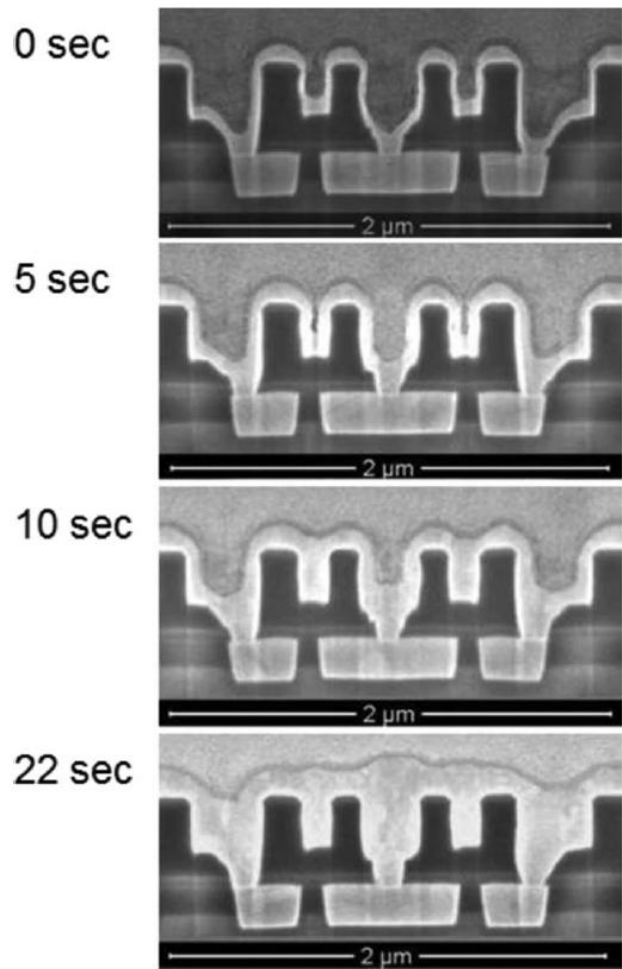


Humidity 10...85%:



Maskless localized electrodeposition: additives

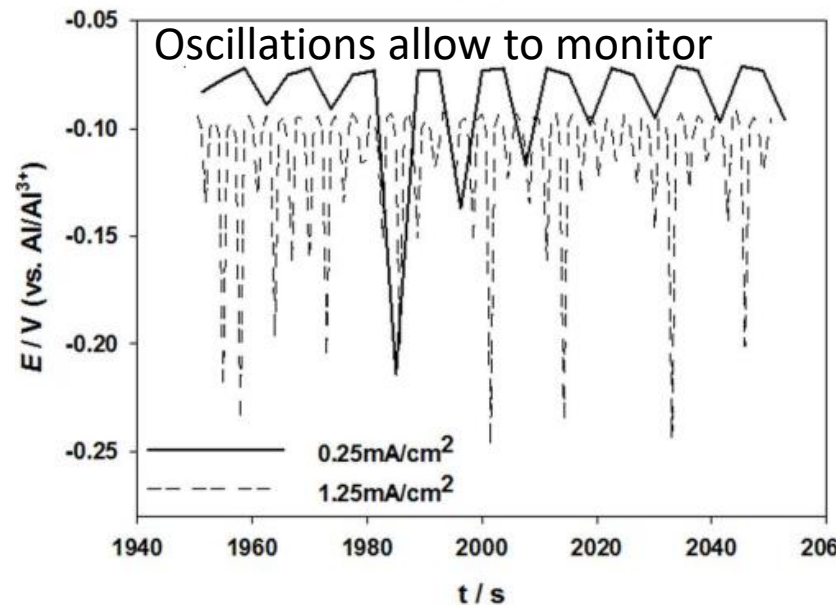
Damascene technology, IBM 1998



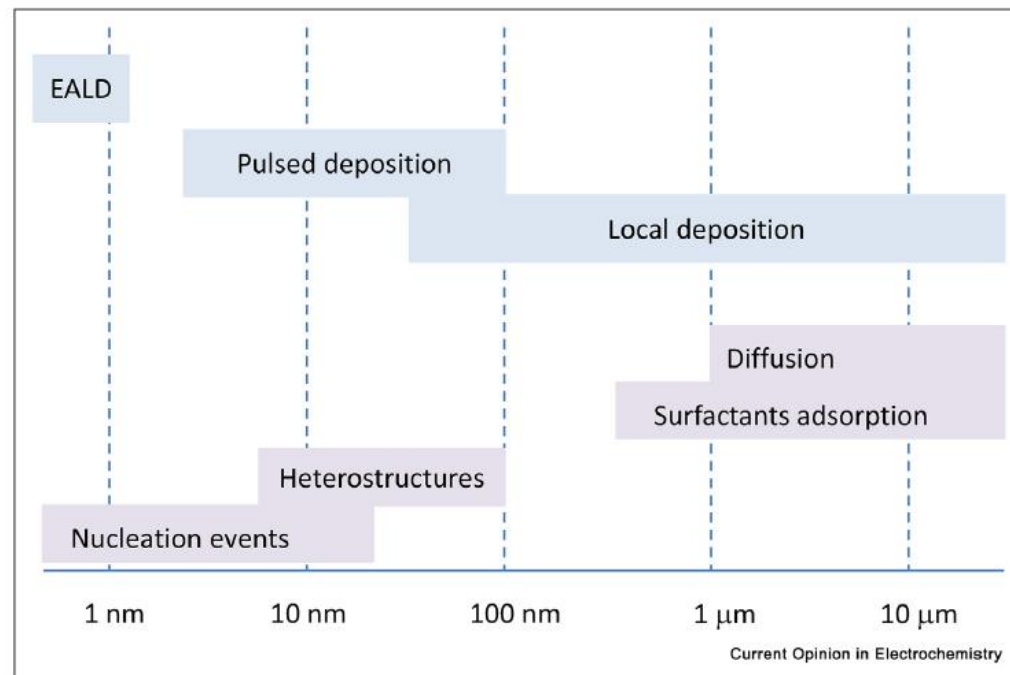
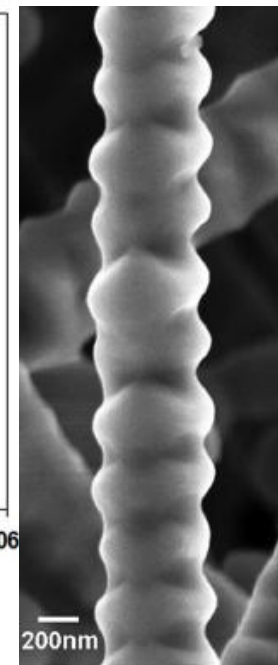
IBM J. Res. Devel. 49 (2005) 3

The secret is to combine adsorbing additives which inhibit and enhance deposition, with different diffusion behaviors.

J. Electrochem. Soc. 163 (2016) D213



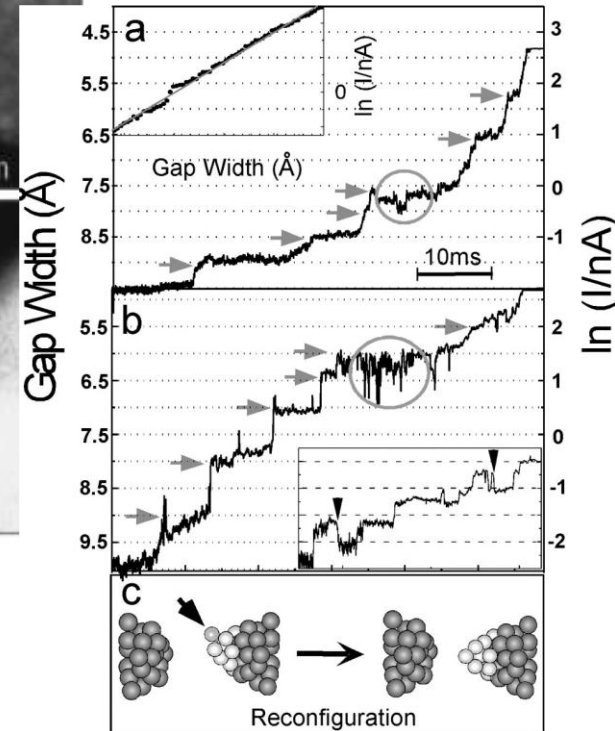
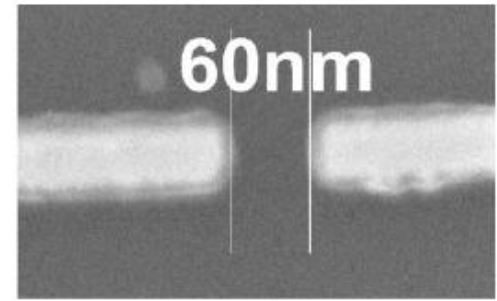
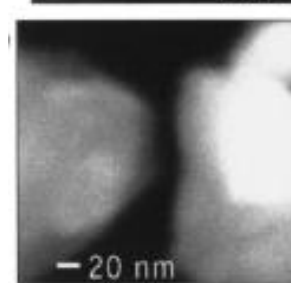
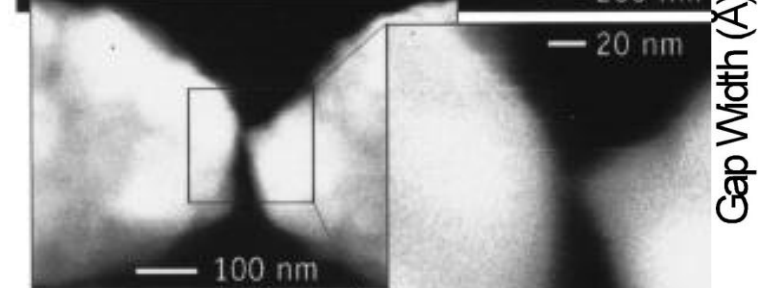
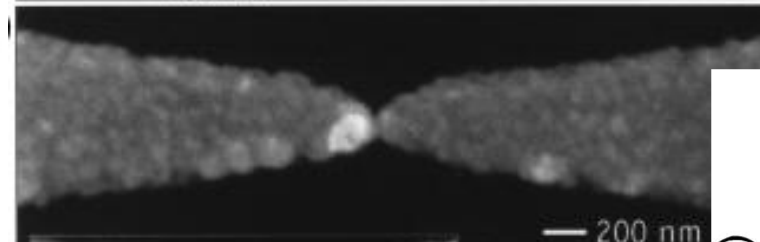
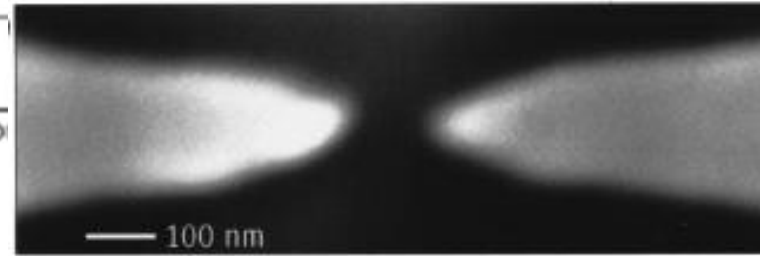
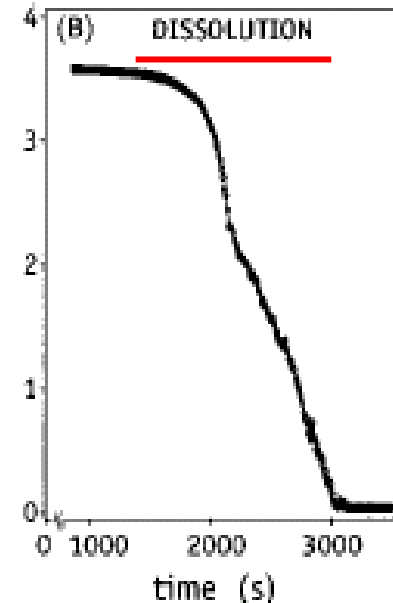
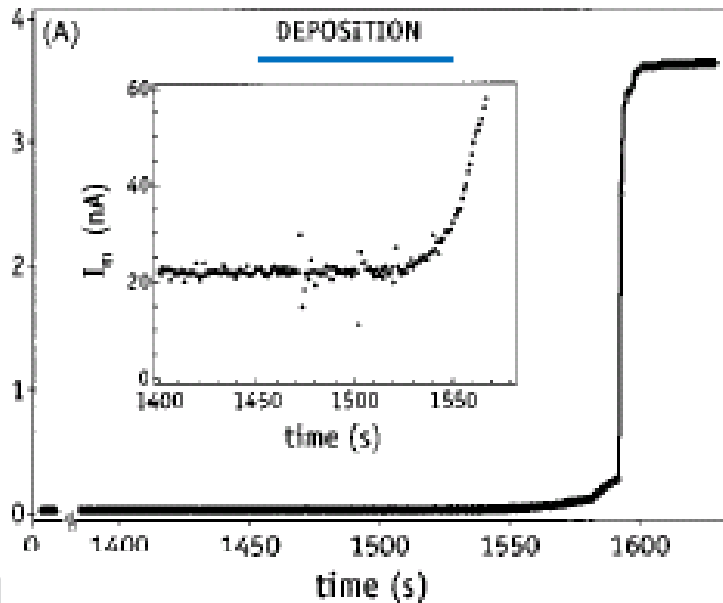
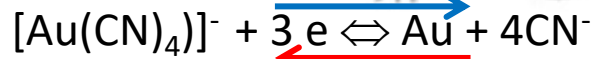
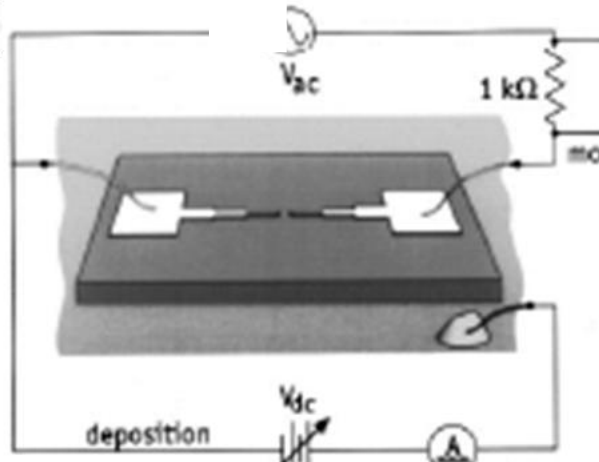
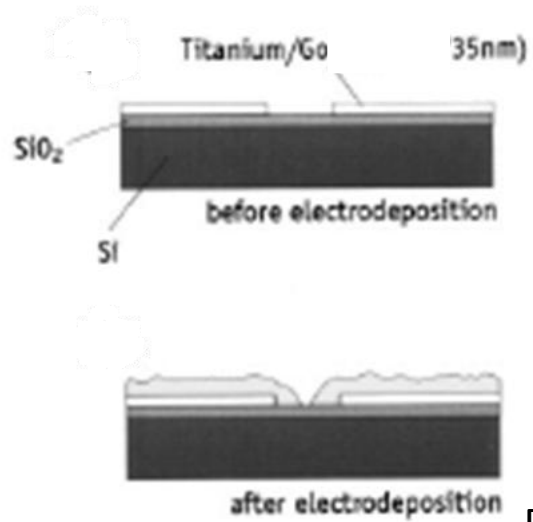
ECS Electrochem. Lett. 4 (2015) D21



Gaps formed by electrodeposition and dissolution due to specific distribution of current lines

Resistance monitoring

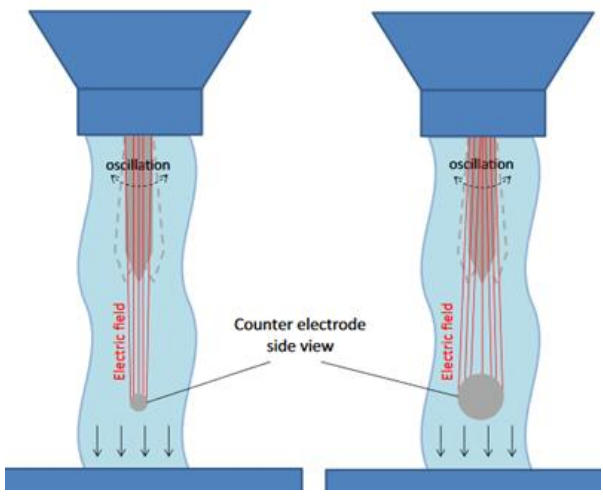
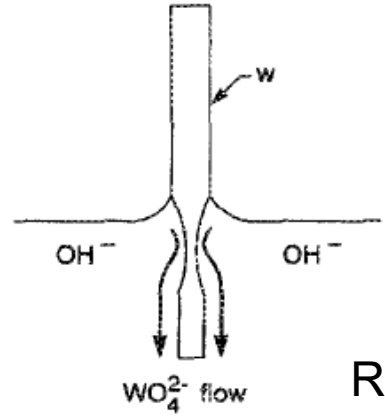
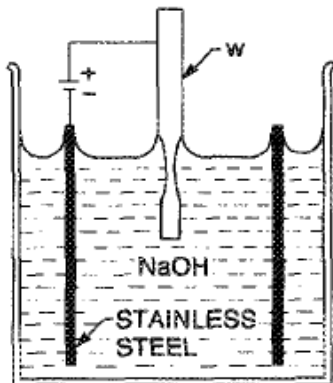
OR tunneling current feedback



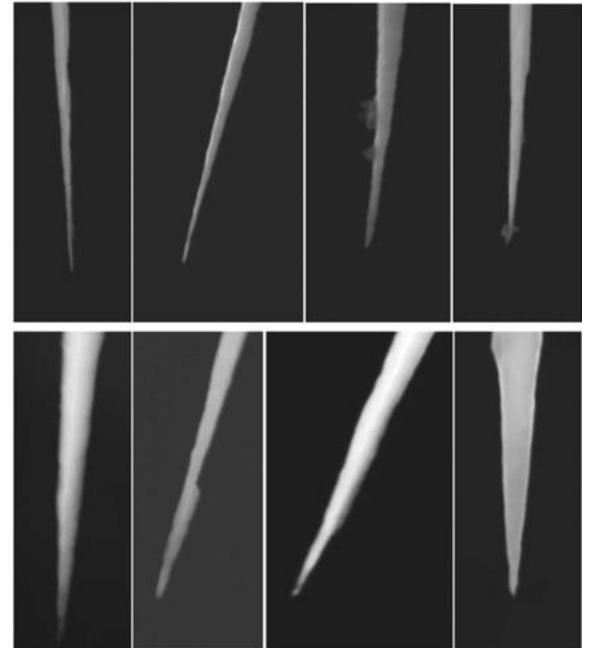
Appl. Phys. Lett
74 (1999) 2084

Appl. Phys. Lett
72 (1998) 894

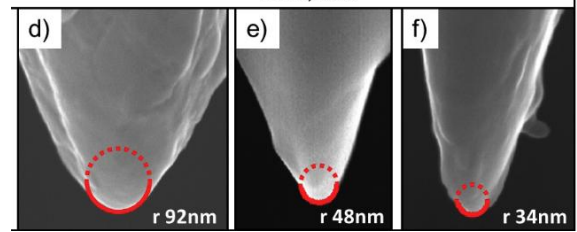
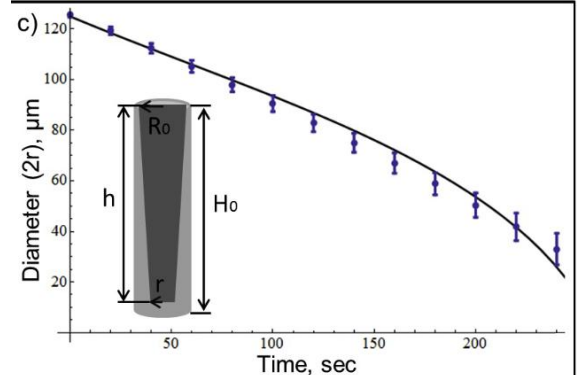
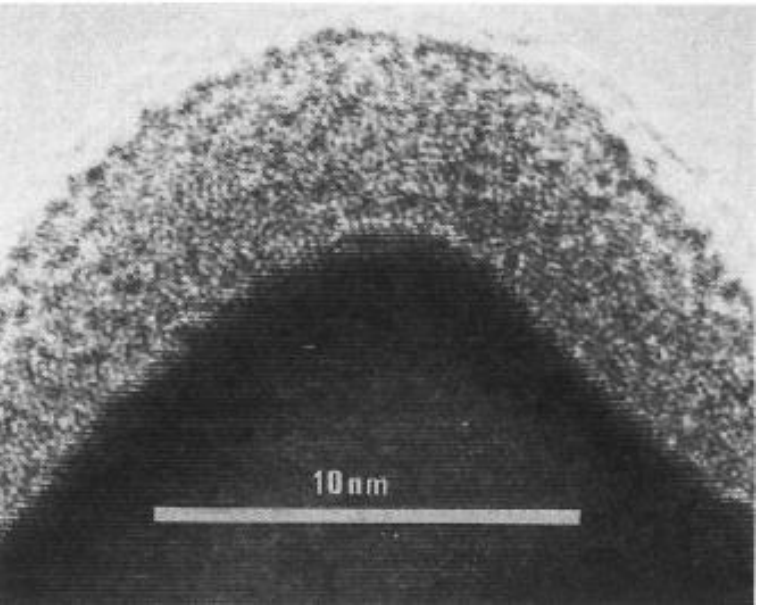
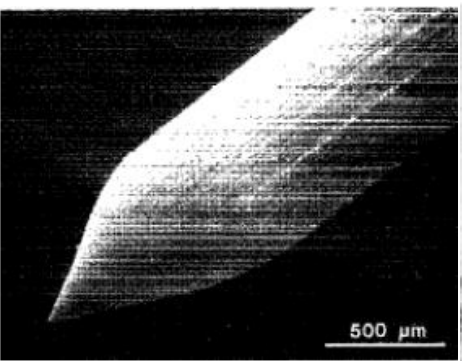
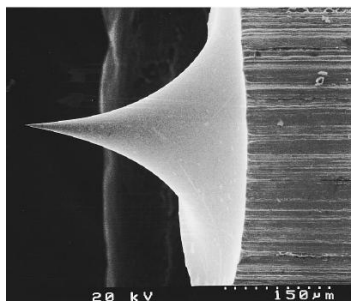
Anodic etching of tips (probes) due to specific distribution of current lines and diffusion flows



Rev. Sci. Instrum.85 (2014) 095109



Tungsten: NaOH, KOH; Pt-Ir: alkali with cyanide additives

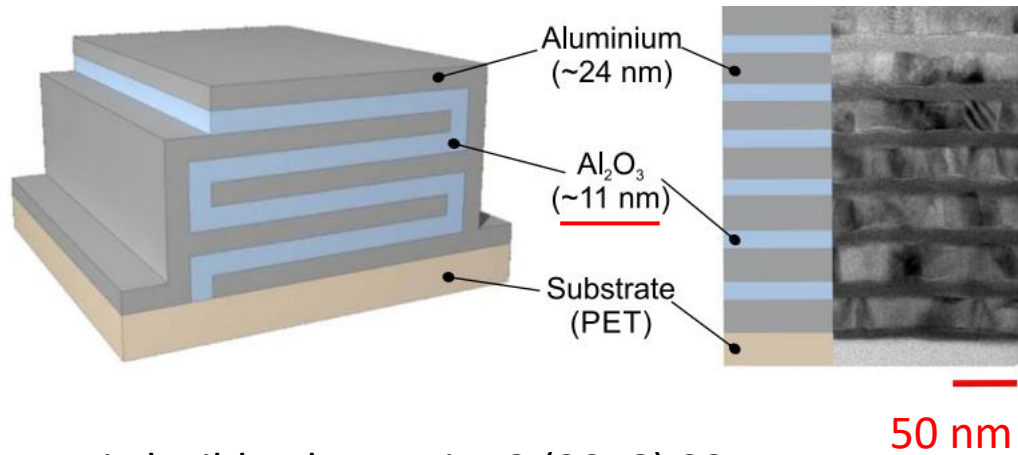


J.Vac.Sci.Technol.
B 14(1996)1

Rev.Sci.Instrum.
64 (1993) 159

Nanotechnology
24(2013) 355702

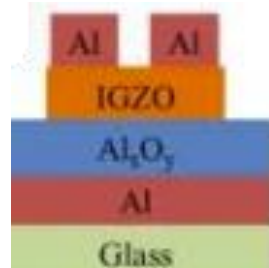
Anodization (oxidation with formation of insoluble products)



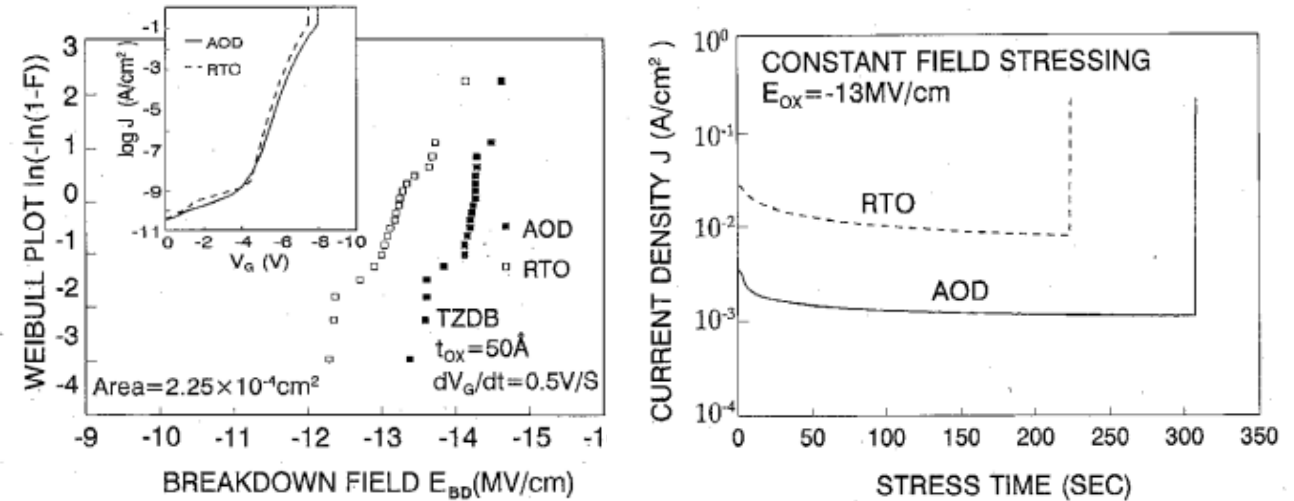
npj Flexible Electronics 2 (2018) 23

Device	A	B	C
Anodization voltage (V)	1.54	2.30	3.08
Approximate Al_xO_y thickness (nm)	2	3	4
C/A (nF/cm ²)	1100	1000	875
Current on/off ratio	7.2×10^5	1.6×10^6	2.1×10^6
SS (mV/dec)	75	68	70
D_{it} (cm ⁻² eV ⁻¹)	1.7×10^{12}	8.5×10^{11}	9.2×10^{11}
RMS roughness (nm)	1.58	1.54	1.53
V_{TH} (V)	0.52	0.48	0.51
μ (cm ² /Vs)	~4.3	~5.4	~3.5

IEE Electron Device Lett. 39 (2018) 375



Comparison of anodization + rapid thermal densification (ADO) and rapid thermal oxidation (RTO):



IEE Electron Device Lett. 17 (1996) 575

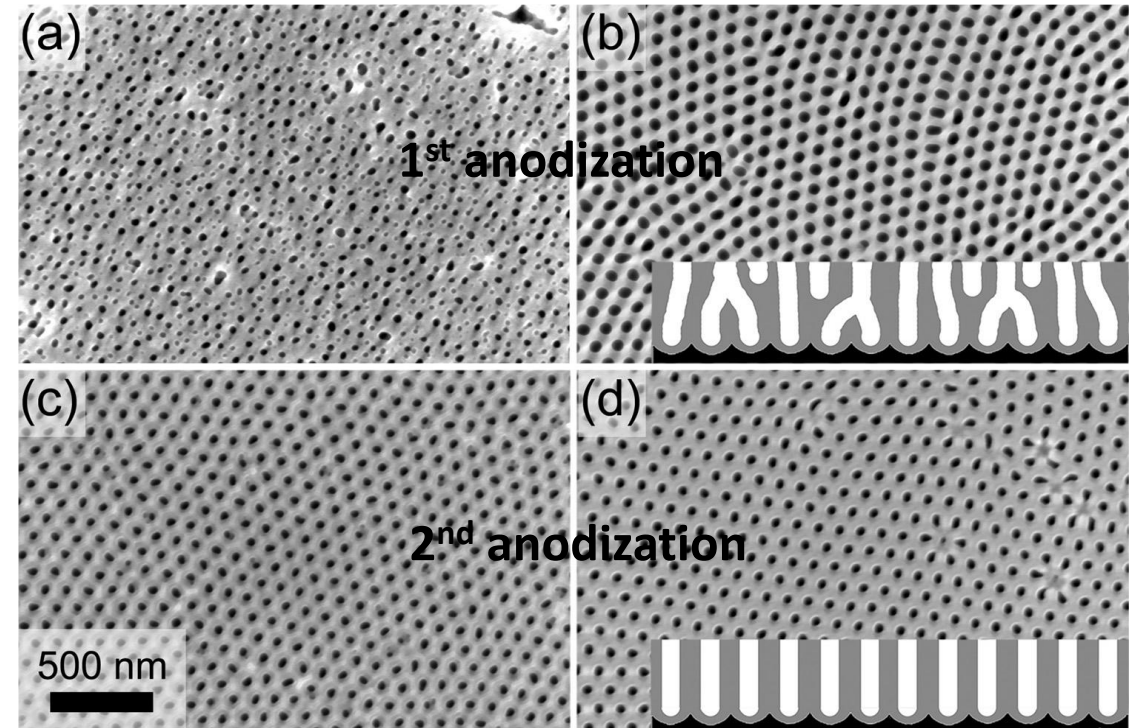
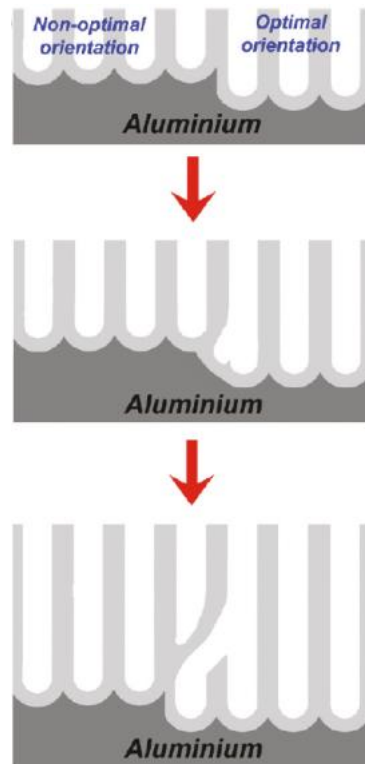
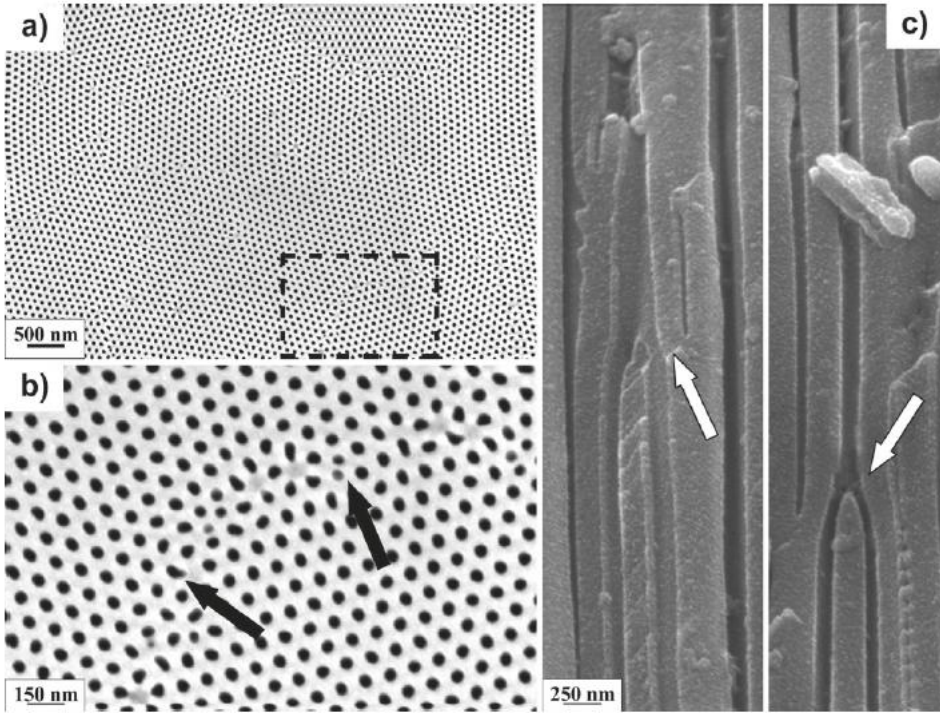
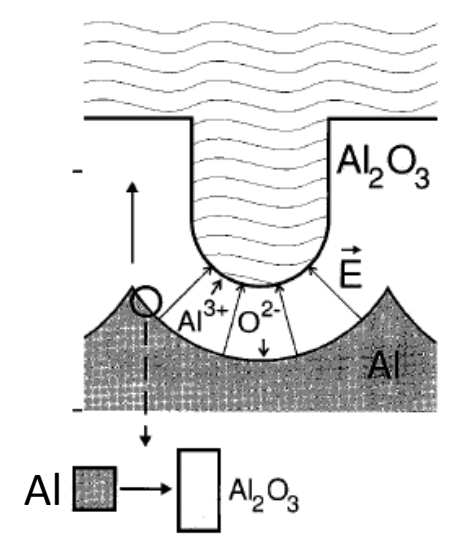
- Anodic oxides can contain water (more for Al and Si, than for Ta, Nb, etc.).
- Anodic oxides formation cannot be done at constant potential because of essential Ohmic contribution.
- However it can be done at room temperature.

Anodization, ordered arrays of pores in aluminum oxide

Al oxide (AAO) is already commercialized,

but for templating we still need home-made.

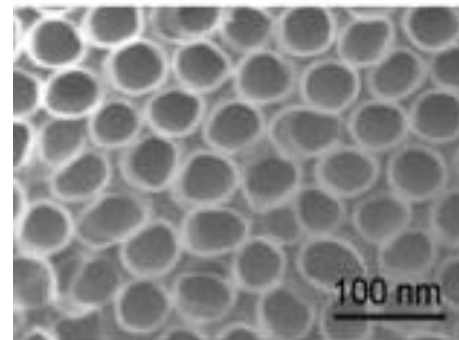
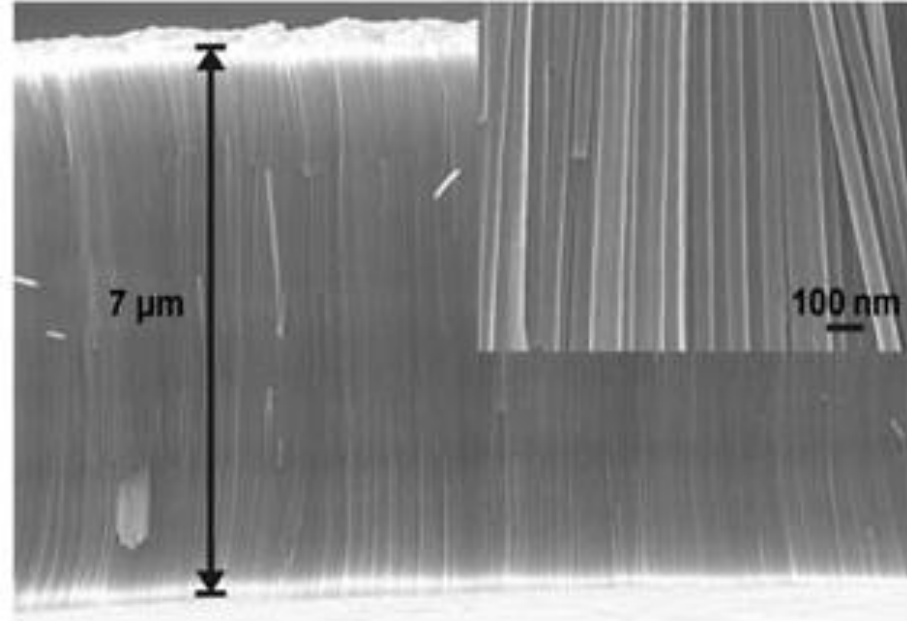
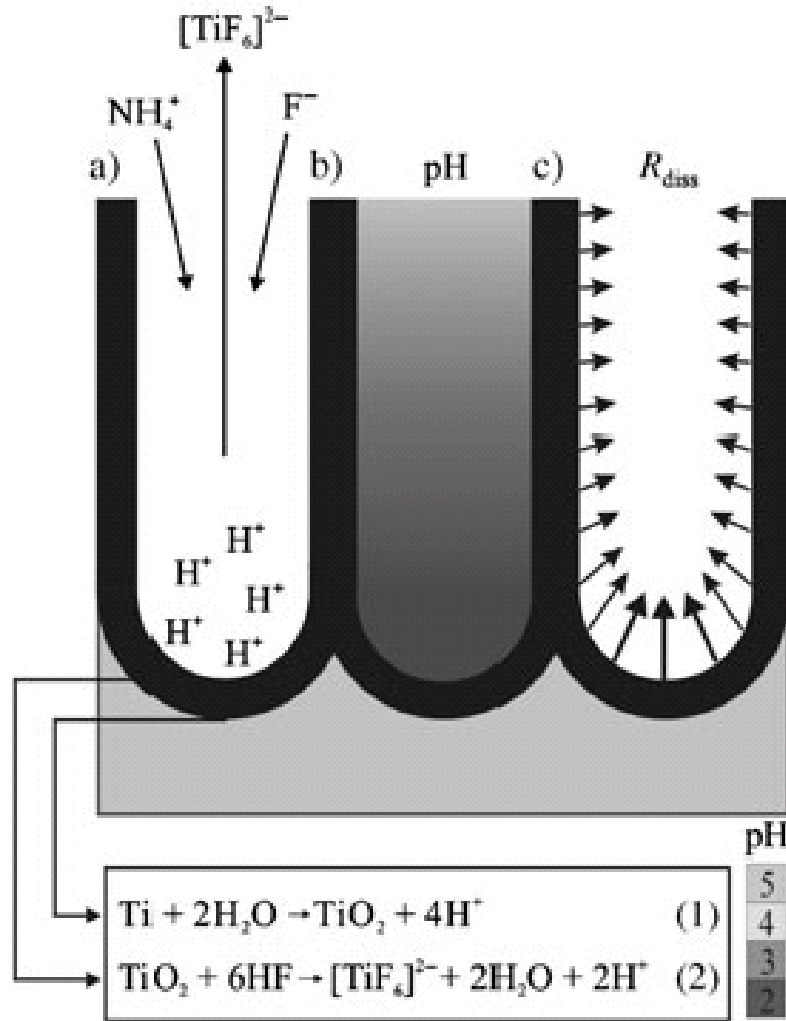
SPI Supplies		Pore Geometries for Isotropic AAO Membranes					
Parameter							Tolerance
Pore Diameter (nm)	10	20	40	100	200		$\pm(10\%+2\text{nm})$
Pore Period (nm)	26	44	107	250	470		$\pm(15\%+5\text{nm})$
Pore Density (cm ⁻²)	$1.6 \cdot 10^{11}$	$5.8 \cdot 10^{10}$	$1.0 \cdot 10^{10}$	$2 \cdot 10^9$	$5 \cdot 10^8$		$\pm 20\%$
Porosity (%)	12	12	12	15	15		± 3



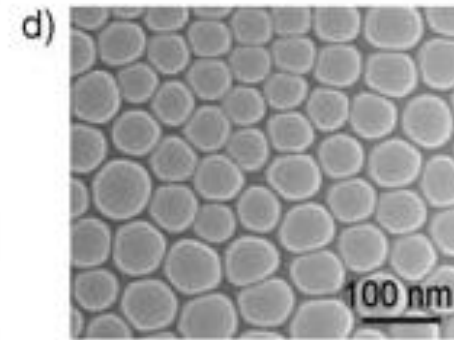
J. Phys. Chem. C 115 (2011) 23726

Electrochim. Acta 226 (2017) 60

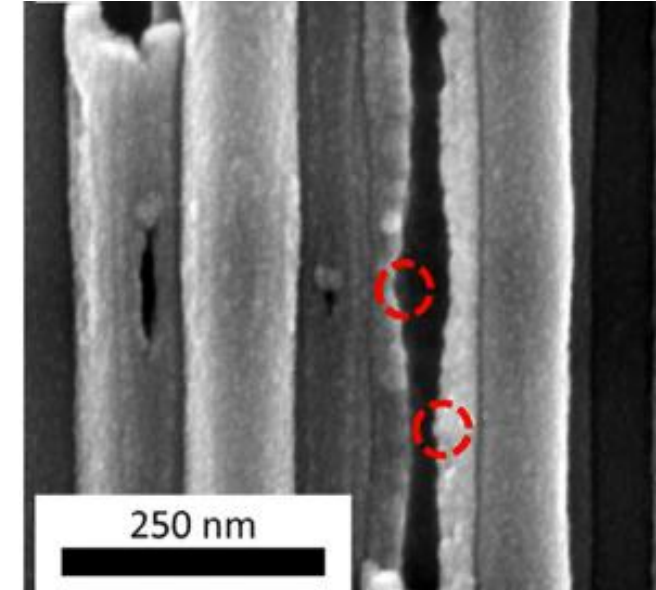
Anodization, less ordered pores in titanium oxide



External surface



Bottom



1D photonic crystals:
periodically varied pore diameter

Scripta Mater. 178 (2020) 13

To conclude:

- useful **nm-size** fragments can be fabricated by electrochemical room-temperature techniques;
- some of them can be assembled to obtain useful devices;
- many useful things can be done in **μm-size** scale;
- controllability can be further increased, by involving the knowledge of electrochemical kinetics.